

# LMZ34002 QFNパッケージ、4.5V~40V入力の 15W負電圧出力パワー・モジュール

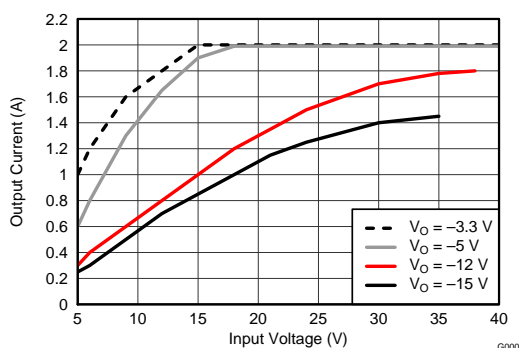
## 1 特長

- 小さな占有面積で低プロファイルの設計を可能にする完全な統合電源ソリューション
- 広い入力電圧範囲: 4.5V~40V
- 出力電圧を-3V~-17Vの範囲で設定可能
- 最大2Aの出力電流を供給
- 45Vのサージ耐圧
- 外部クロックに同期
- 調整可能なスロー・スタート
- 低電圧誤動作防止(UVLO)をプログラム可能
- 出力過電流保護
- 過熱保護機能
- 動作温度範囲: -40°C~+85°C
- 強化された熱特性: 14°C/W
- EN55022 Class Bの放射要件に準拠  
- シールド付きインダクタを内蔵
- 設計支援については、<http://www.ti.com/product/lmz34002>を参照
- WEBENCH® Power Designerにより、LMZ34002を使用するカスタム設計を作成

## 2 アプリケーション

- 産業用およびモータ制御
- 自動テスト機器
- オーディオ/ビデオ用のバイポーラ・アンプ
- 高密度の電源システム

安全な動作電流

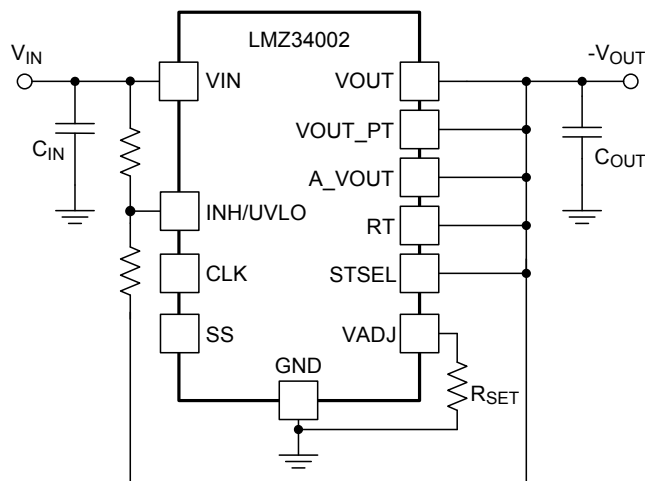


## 3 概要

LMZ34002 SIMPLE SWITCHER®パワー・モジュールは、使いやすい負電圧出力のパワー・モジュールで、15WのDC/DCコンバータとシールド付きインダクタ、パッシブ部品を組み合わせて、低プロファイルのQFNパッケージに封入しています。外部部品は5個しか使用せず、ループ補償や磁気部品の選択プロセスも不要になります。

9mm×11mm×2.8mmのQFNパッケージはプリント基板へ簡単にハンダ付けでき、部品数を減らすとともに優れた消費電力特性を実現できます。LMZ34002は、ディスクリート設計と同等の柔軟性および機能セットを備え、負出力電圧を必要とする幅広い範囲のICおよびアナログ回路への電力供給に最適です。先進のパッケージング技術により、標準のQFN実装/試験手法に対応した、堅牢で信頼性の高い電源ソリューションを実現できます。

アプリケーション概略図



## 4 Specifications

### 4.1 Absolute Maximum Ratings<sup>(1)</sup>

over operating temperature range (unless otherwise noted)

		MIN	MAX	UNIT
Input Voltage	VIN	-0.3	45	V
	INH/UVLO	-0.3	5 <sup>(2)</sup>	V
	VADJ	-0.3	3 <sup>(2)</sup>	V
	SS	-0.3	3 <sup>(2)</sup>	V
	STSEL	-0.3	3 <sup>(2)</sup>	V
	RT	-0.3	3.6 <sup>(2)</sup>	V
	CLK	-0.3	3.6 <sup>(2)</sup>	V
Output Voltage	PH	-0.6	45	V
	PH 10ns Transient	-2	45	V
	VOUT	-0.6	VIN <sup>(2)</sup>	V
V <sub>DIFF</sub> (VOUT to exposed thermal pad)			±200	mV
Source Current	INH/UVLO		100	µA
Sink Current	SS		200	µA
Operating Junction Temperature		-40	105 <sup>(3)</sup>	°C
Storage Temperature		-65	150	°C
Peak Reflow Case Temperature <sup>(4)</sup>			250 <sup>(5)</sup>	°C
Maximum Number of Reflows Allowed <sup>(4)</sup>			3 <sup>(5)</sup>	
Mechanical Shock	Mil-STD-883D, Method 2002.3, 1 ms, 1/2 sine, mounted		1500	G
Mechanical Vibration	Mil-STD-883D, Method 2007.2, 20-2000Hz		20	

(1) Stresses beyond those listed under absolute maximum ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under recommended operating conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) This voltage rating is referenced to A\_VOUT, not GND.

(3) See the temperature derating curves in the Typical Characteristics section for thermal information.

(4) For soldering specifications, refer to the [Soldering Requirements for BQFN Packages](#) application note.

(5) Devices with a date code prior to week 14 2018 (1814) have a peak reflow case temperature of 240°C with a maximum of one reflow.

### 4.2 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V <sub>IN</sub>	Input Voltage	4.5	40	V
V <sub>OUT</sub>	Output Voltage	-3	-17	V

### 4.3 Thermal Information

THERMAL METRIC <sup>(1)</sup>		LMZ34002	UNIT
		RKG	
		41 PINS	
$\theta_{JA}$	Junction-to-ambient thermal resistance <sup>(2)</sup>	14	°C/W
$\Psi_{JT}$	Junction-to-top characterization parameter <sup>(3)</sup>	3.3	°C/W
$\Psi_{JB}$	Junction-to-board characterization parameter <sup>(4)</sup>	6.8	°C/W

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) (SPRA953) application report.
- (2) The junction-to-ambient thermal resistance,  $\theta_{JA}$ , applies to devices soldered directly to a 100 mm x 100 mm double-sided PCB with 1 oz. copper and natural convection cooling. Additional airflow reduces  $\theta_{JA}$ .
- (3) The junction-to-top characterization parameter,  $\Psi_{JT}$ , estimates the junction temperature,  $T_J$ , of a device in a real system, using a procedure described in JESD51-2A (sections 6 and 7).  $T_J = \Psi_{JT} * P_{dis} + T_T$ ; where  $P_{dis}$  is the power dissipated in the device and  $T_T$  is the temperature of the top of the device.
- (4) The junction-to-board characterization parameter,  $\Psi_{JB}$ , estimates the junction temperature,  $T_J$ , of a device in a real system, using a procedure described in JESD51-2A (sections 6 and 7).  $T_J = \Psi_{JB} * P_{dis} + T_B$ ; where  $P_{dis}$  is the power dissipated in the device and  $T_B$  is the temperature of the board 1mm from the device.

### 4.4 Package Specifications

LMZ34002		UNIT
Weight		0.9 grams
Flammability	Meets UL 94 V-O	
MTBF Calculated reliability	Per Bellcore TR-332, 50% stress, $T_A = 40^\circ\text{C}$ , ground benign	31.7 Mhrs

### 4.5 Electrical Characteristics

 $-40^\circ\text{C} \leq T_A \leq +85^\circ\text{C}$ ,  $V_{IN} = 12\text{ V}$ ,  $V_{OUT} = -5\text{ V}$ ,  $I_{OUT} = 2\text{ A}$ 
 $C_{IN} = 2 \times 2.2\ \mu\text{F}$  ceramic,  $C_{OUT} = 2 \times 47\ \mu\text{F}$  ceramic (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$I_{OUT}$	Output current	Over input voltage and output voltage range	0 <sup>(1)</sup>		2 <sup>(2)</sup>	A
$V_{IN}$	Input voltage range	Over output current range	4.5		40 <sup>(3)</sup>	V
UVLO	$V_{IN}$ Undervoltage lockout	Rising only, $R_{UVLO1} = 174\ \text{k}\Omega$ , $R_{UVLO2} = 63.4\ \text{k}\Omega$		4.5		V
$V_{OUT(adj)}$	Output voltage adjust range	Over output current range	-3		-17 <sup>(3)</sup>	V
$V_{OUT}$	Set-point voltage tolerance	$T_A = 25^\circ\text{C}$ , $I_{OUT} = 100\ \text{mA}$			2.0% <sup>(4)</sup>	
	Temperature variation	$-40^\circ\text{C} \leq T_A \leq +85^\circ\text{C}$		$\pm 0.5\%$	$\pm 1\%$	
	Line regulation	Over input voltage range		$\pm 0.1\%$		
	Load regulation	From 100 mA to $I_{OUT(max)}$		$\pm 0.4\%$		
	Total output voltage variation	Includes set-point, line, load, and temperature variation				3% <sup>(4)</sup>
$\eta$	Efficiency	$V_{IN} = 24\text{ V}$	$V_{OUT} = -12\text{ V}$ , $I_{OUT} = 1.0\text{ A}$		85%	
			$V_{OUT} = -5.0\text{ V}$ , $I_{OUT} = 1.0\text{ A}$		81%	
			$V_{OUT} = -3.3\text{ V}$ , $I_{OUT} = 1.0\text{ A}$		77%	
		$V_{IN} = 12\text{ V}$	$V_{OUT} = -12\text{ V}$ , $I_{OUT} = 0.6\text{ A}$		86%	
			$V_{OUT} = -5.0\text{ V}$ , $I_{OUT} = 1.0\text{ A}$		81%	
			$V_{OUT} = -3.3\text{ V}$ , $I_{OUT} = 1.0\text{ A}$		78%	
Output voltage ripple	20 MHz bandwidth, $100\ \text{mA} \leq I_{OUT} \leq I_{OUT(max)}$		1%		$V_{OUT}$	
$I_{LIM}$	Current limit threshold		3 <sup>(5)</sup>		A	
Transient response	1.0 A/ $\mu\text{s}$ load step from 25 to 75% $I_{OUT(max)}$	Recovery time		500		$\mu\text{s}$
		$V_{OUT}$ over/undershoot		80		mV

- (1) This device can regulate  $V_{OUT}$  down to 0 A, however the ripple may increase due to pulse-skipping at light loads. See [Light-Load Behavior](#) for more information. See [No-Load Operation](#) when operating at 0 A.
- (2) The maximum current is dependant on  $V_{IN}$  and  $V_{OUT}$ , see [Figure 33](#).
- (3) The sum of  $V_{IN} + |V_{OUT}|$  must not exceed 50 V.
- (4) The stated limit of the set-point voltage tolerance includes the tolerance of both the internal voltage reference and the internal adjustment resistor. The overall output voltage tolerance will be affected by the tolerance of the external  $R_{SET}$  resistor.
- (5) This product is not designed to endure a sustained (> 5 sec) over-current condition.

## Electrical Characteristics (continued)

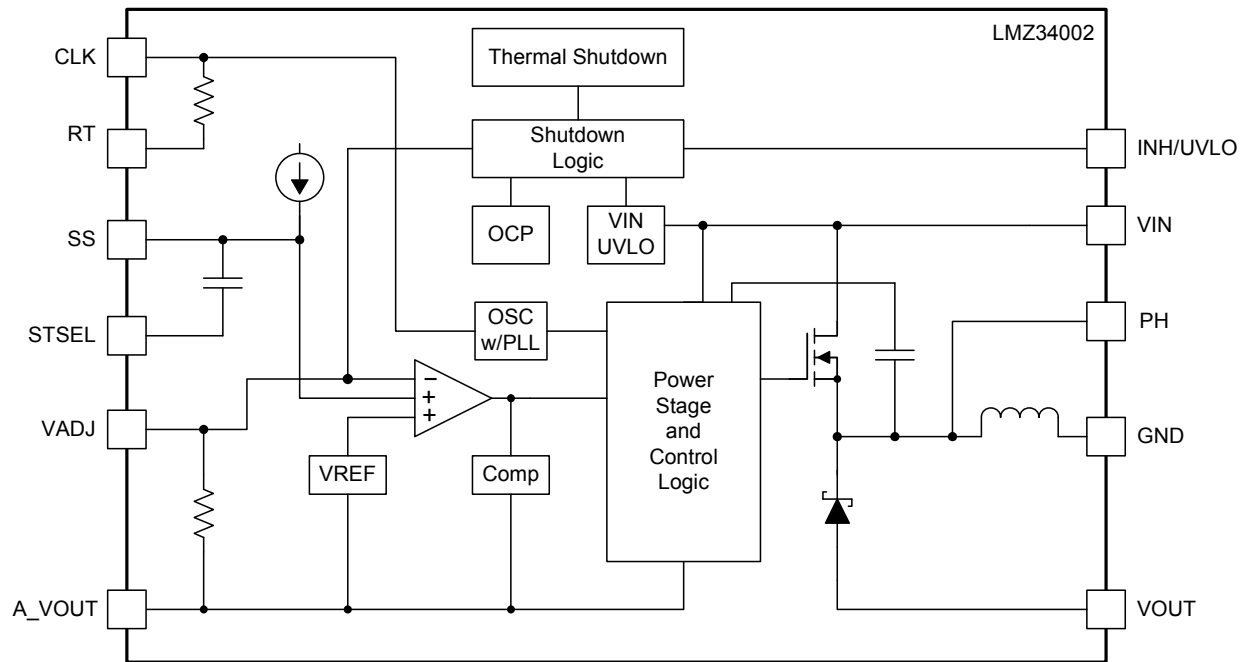
 $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ ,  $V_{\text{IN}} = 12\text{ V}$ ,  $V_{\text{OUT}} = -5\text{ V}$ ,  $I_{\text{OUT}} = 2\text{ A}$ 
 $C_{\text{IN}} = 2 \times 2.2\text{ }\mu\text{F}$  ceramic,  $C_{\text{OUT}} = 2 \times 47\text{ }\mu\text{F}$  ceramic (unless otherwise noted)

PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNIT
$V_{\text{INH}}$	Inhibit threshold voltage	INH with respect to A_VOUT	1.15	1.25	1.36 <sup>(6)</sup>	V
$I_{\text{INH}}$	INH Input current	$V_{\text{INH}} < 1.15\text{ V}$		-0.9		$\mu\text{A}$
		$V_{\text{INH}} > 1.36\text{ V}$		-3.8		$\mu\text{A}$
$I_{\text{I(stby)}}$	Input standby current	INH pin to A_VOUT		1.3	4	$\mu\text{A}$
$f_{\text{SW}}$	Switching frequency	RT pin to A_VOUT	700	800	900	kHz
$f_{\text{CLK}}$	Synchronization frequency	$R_{\text{RT}} = 0\text{ }\Omega$	700 <sup>(7)</sup>		900 <sup>(7)</sup>	kHz
		$R_{\text{RT}} = 93.1\text{ k}\Omega$	400 <sup>(7)</sup>		600 <sup>(7)</sup>	kHz
$V_{\text{CLK-H}}$	CLK High-Level Threshold	With respect to A_VOUT		1.9	2.2	V
$V_{\text{CLK-L}}$	CLK Low-Level Threshold	With respect to A_VOUT	0.5	0.7		V
$D_{\text{CLK}}$	CLK Duty cycle		25%	50%	75%	
	Thermal Shutdown	Thermal shutdown		180		$^{\circ}\text{C}$
		Thermal shutdown hysteresis		15		$^{\circ}\text{C}$
$C_{\text{IN}}$	External input capacitance	Ceramic	4.7 <sup>(8)</sup>	10		$\mu\text{F}$
		Non-ceramic		22		
$C_{\text{OUT}}$	External output capacitance		100 <sup>(9)</sup>		430 <sup>(9)</sup>	$\mu\text{F}$

- (6) If this pin is left open circuit, the device operates when input power is applied. An external level-shifter is required to interface with this pin. See [Output On/Off Inhibit \(INH\)](#) for further guidance.
- (7) The synchronization frequency is dependant on  $V_{\text{IN}}$  and  $V_{\text{OUT}}$  as shown in [Switching Frequency](#).  $R_{\text{RT}}$  must be either  $0\text{ }\Omega$  or  $93.1\text{ k}\Omega$ .
- (8) A minimum of  $4.7\text{ }\mu\text{F}$  of ceramic external capacitance is required across the input ( $V_{\text{IN}}$  and PGND connected) for proper operation. Locate the capacitor close to the device. See [Table 1](#) for more details.
- (9) The amount of required capacitance must include at least  $2 \times 47\text{ }\mu\text{F}$  ceramic capacitor (or  $4 \times 22\text{ }\mu\text{F}$ ). Locate the capacitance close to the device. Adding additional capacitance close to the load improves the response of the regulator to load transients. See [Table 1](#) for more details. See [Inrush Current](#) section when adding additional output capacitance.

## 5 Device Information

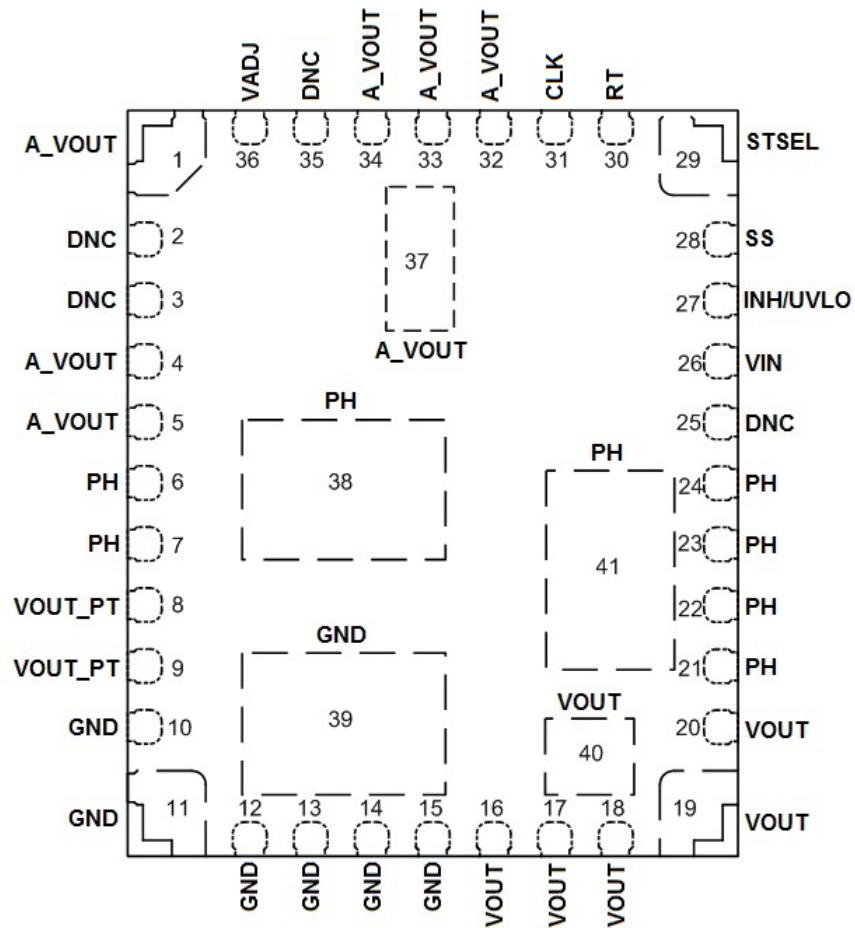
Functional Block Diagram



### Pin Functions

TERMINAL		DESCRIPTION
NAME	NO.	
VIN	26	Input voltage. This pin supplies all power to the converter. Connect this pin to the input supply and connect bypass capacitors between this pin and GND.
VOUT	16	Negative output voltage with respect to GND. Connect these pins to the output load and connect external bypass capacitors between these pins and GND. Pad 40 should be connected to PCB VOUT planes using multiple vias for good thermal performance.
	17	
	18	
	19	
	20	
GND	40	This is the return current path for the power stage of the device. These pins are connected to the internal output inductor. Connect these pins to the load and to the bypass capacitors associated with VIN and VOUT.
	10	
	11	
	12	
	13	
	14	
	15	
PH	39	Phase switch node. Do not place any external component on these pins or tie them to a pin of another function.
	6	
	7	
	21	
	22	
	23	
	24	
VOUT_PT	8	VOUT and A_VOUT Connection Point. Connect VOUT to A_VOUT at these pins as shown in the <a href="#">Layout Considerations</a> section. These pins are not connected to internal circuitry, and are not connected to one other.
	9	
DNC	2	Do Not Connect. Do not connect these pins to GND, to another DNC pin, or to any other voltage. These pins are connected to internal circuitry. Each pin must be soldered to an isolated pad.
	3	
	25	
	35	
A_VOUT	1	These pins are connected to the internal analog reference (A_VOUT) of the device. This node should be treated as the negative voltage reference for the analog control circuitry. Pad 37 should be connected to the PCB A_VOUT plane using multiple vias for good thermal performance. Not all pins are connected together internally. All pins must be connected together externally with a copper plane or pour directly under the module. Connect A_VOUT to VOUT at a single point (VOUT_PT; pins 8 & 9). See <a href="#">Layout Recommendations</a> .
	4	
	5	
	32	
	33	
	34	
37		
RT	30	Switching frequency adjust pin. To operate at the recommended free-running frequency, connect this pin to A_VOUT. Connecting a resistor between this pin and A_VOUT will reduce the switching frequency. See <a href="#">Switching Frequency</a> section.
CLK	31	Use this pin to synchronize to an external clock. If unused, isolate this pin from any other signal.
INH/UVLO	27	Inhibit and UVLO adjust pin. Use an external level-shifter device to ground this pin to control the INH function. A resistor divider between this pin, A_VOUT, and VIN sets the UVLO voltage.
SS	28	Slow-start pin. Connecting an external capacitor between this pin and A_VOUT adjusts the output voltage rise time.
STSEL	29	Slow-start select. Connect this pin to A_VOUT to enable the internal SS capacitor.
VADJ	36	Connecting a resistor between this pin and GND sets the output voltage. A dedicated GND sense line connected at the load will improve regulation at the load. See <a href="#">Figure 48</a> in the <a href="#">Layout Considerations</a> section.

RKG PACKAGE  
(TOP VIEW)



## 6 Typical Characteristics (VIN = 5 V)

The electrical characteristic data has been developed from actual products tested at 25°C. This data is considered typical for the converter. Applies to Figure 1, Figure 2, and Figure 3. The temperature derating curves represent the conditions at which internal components are at or below the manufacturer's maximum operating temperatures. Derating limits apply to devices soldered directly to a 100 mm × 100 mm, 4-layer, double-sided PCB with 1 oz. copper. Applies to Figure 4, Figure 5, and Figure 6.

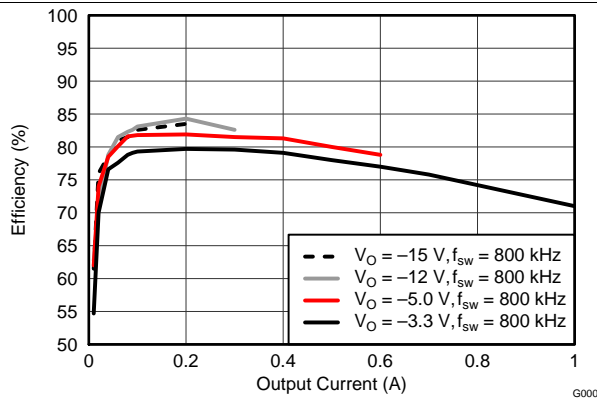


Figure 1. Efficiency vs. Output Current

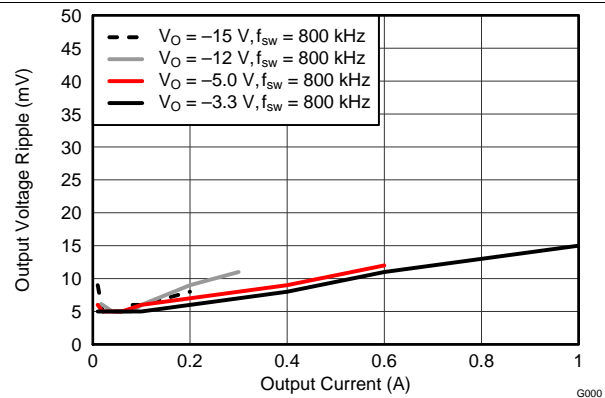


Figure 2. Voltage Ripple vs. Output Current

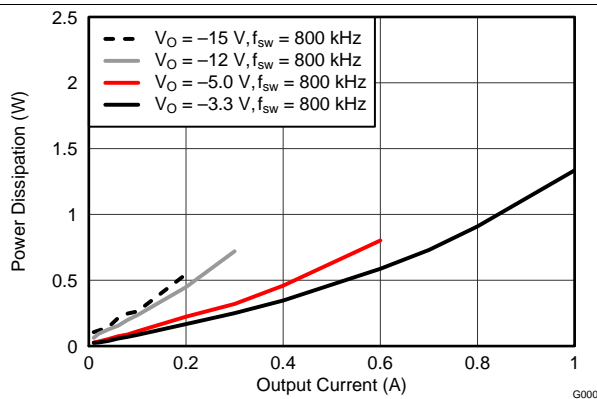


Figure 3. Power Dissipation vs. Output Current

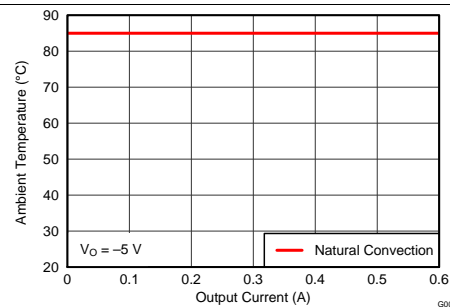


Figure 4. Safe Operating Area

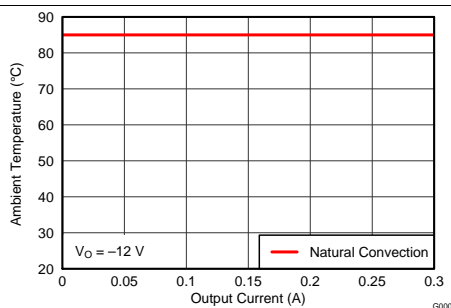


Figure 5. Safe Operating Area

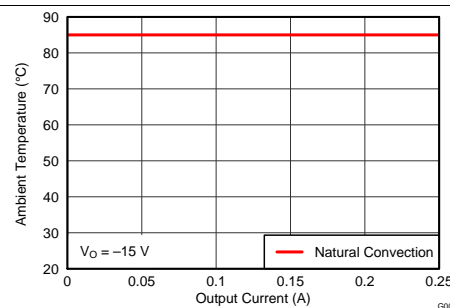


Figure 6. Safe Operating Area



## 7 Typical Characteristics (VIN = 12 V)

The electrical characteristic data has been developed from actual products tested at 25°C. This data is considered typical for the converter. Applies to [Figure 7](#), [Figure 8](#), and [Figure 9](#). The temperature derating curves represent the conditions at which internal components are at or below the manufacturer's maximum operating temperatures. Derating limits apply to devices soldered directly to a 100 mm × 100 mm, 4-layer, double-sided PCB with 1 oz. copper. Applies to [Figure 10](#), [Figure 11](#), and [Figure 12](#).

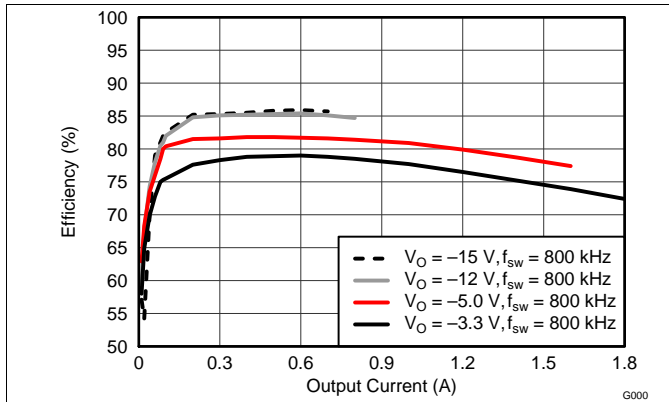


Figure 7. Efficiency vs. Output Current

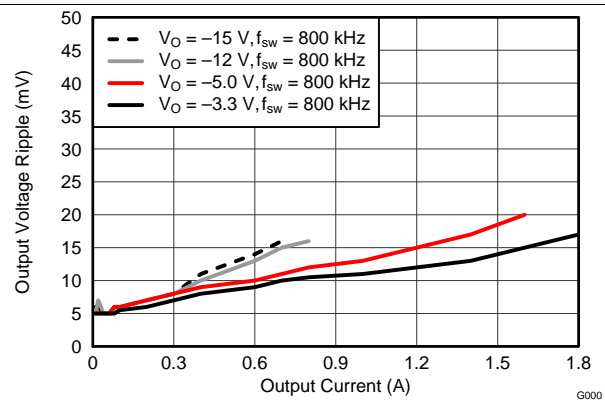


Figure 8. Voltage Ripple vs. Output Current

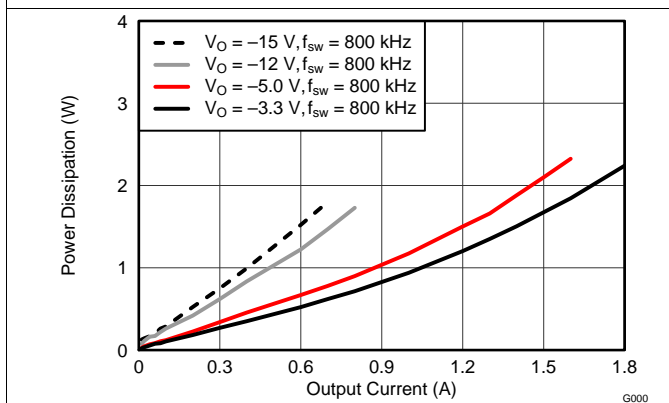


Figure 9. Power Dissipation vs. Output Current

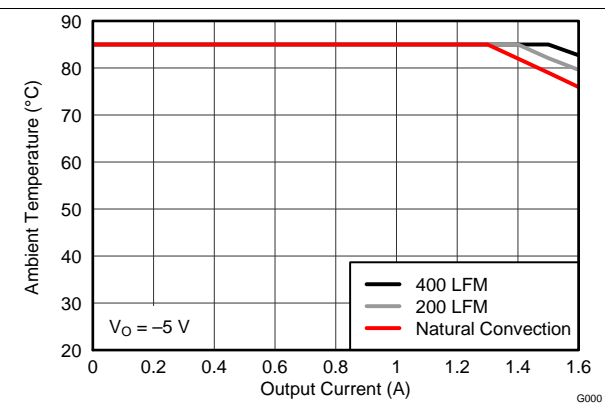


Figure 10. Safe Operating Area

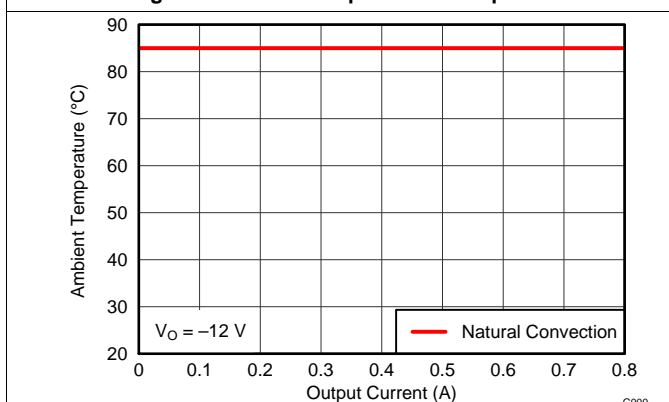


Figure 11. Safe Operating Area

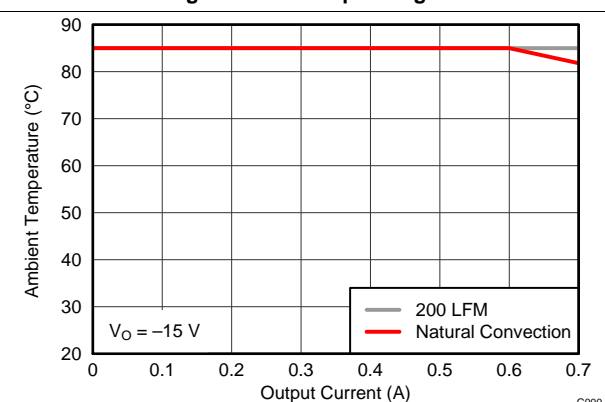


Figure 12. Safe Operating Area

## 8 Typical Characteristics (VIN = 24 V)

The electrical characteristic data has been developed from actual products tested at 25°C. This data is considered typical for the converter. Applies to Figure 13, Figure 14, and Figure 15. At light load the output voltage ripple may increase due to pulse skipping. See [Light-Load Behavior](#) for more information. Applies to Figure 14. The temperature derating curves represent the conditions at which internal components are at or below the manufacturer's maximum operating temperatures. Derating limits apply to devices soldered directly to a 100 mm × 100 mm, 4-layer, double-sided PCB with 1 oz. copper. Applies to Figure 16, Figure 17, and Figure 18.

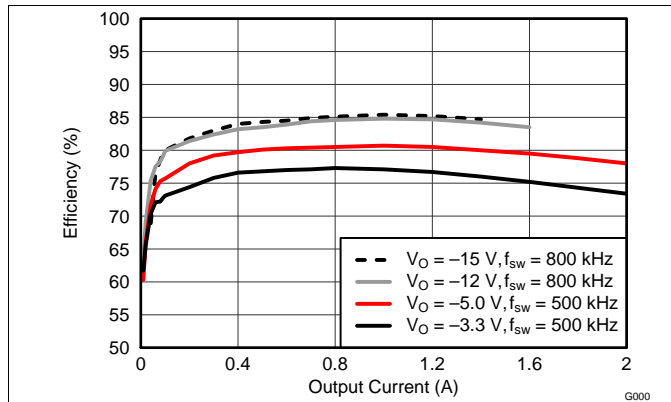


Figure 13. Efficiency vs. Output Current

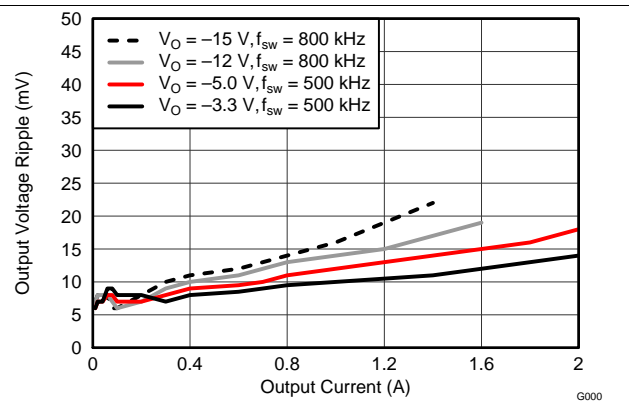


Figure 14. Voltage Ripple vs. Output Current

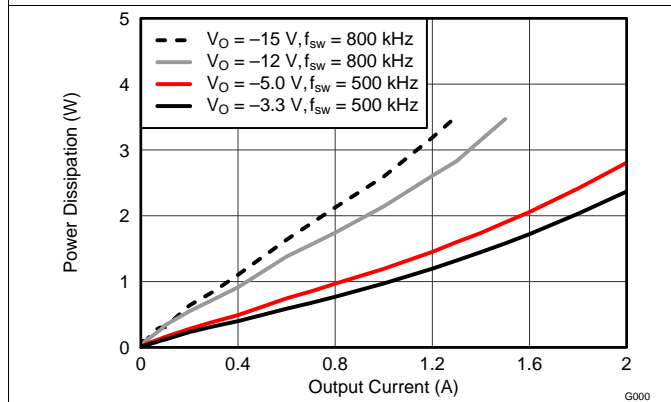


Figure 15. Power Dissipation vs. Output Current

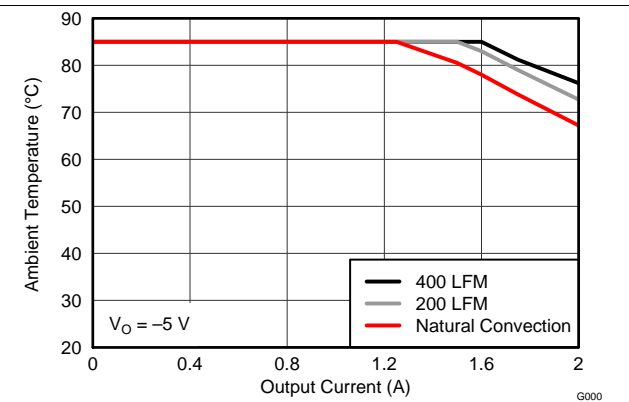


Figure 16. Safe Operating Area

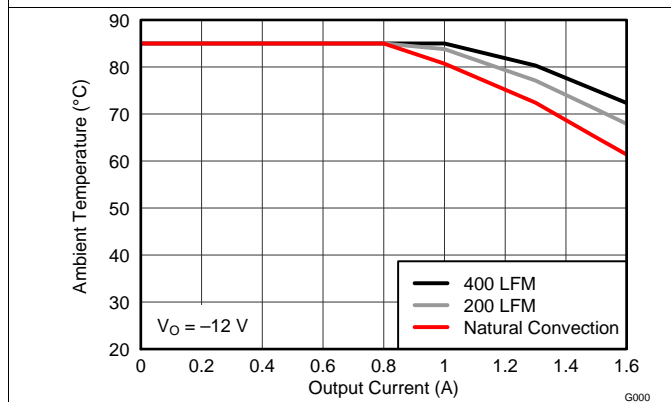


Figure 17. Safe Operating Area

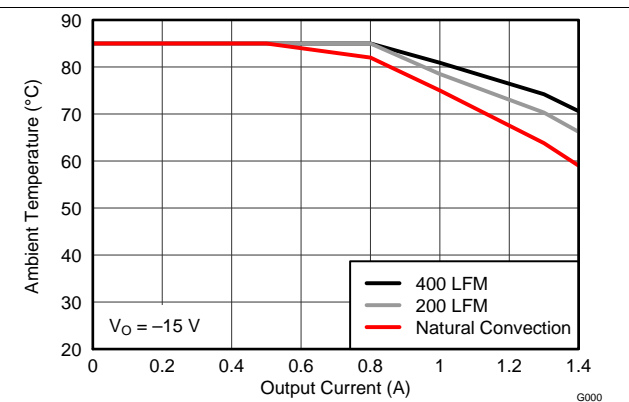


Figure 18. Safe Operating Area

## 9 Typical Characteristics (VIN = 36 V)

The electrical characteristic data has been developed from actual products tested at 25°C. This data is considered typical for the converter. Applies to Figure 19, Figure 20, and Figure 21. At light load the output voltage ripple may increase due to pulse skipping. See [Light-Load Behavior](#) for more information. Applies to Figure 20. The temperature derating curves represent the conditions at which internal components are at or below the manufacturer's maximum operating temperatures. Derating limits apply to devices soldered directly to a 100 mm × 100 mm, 4-layer, double-sided PCB with 1 oz. copper. Applies to Figure 22, Figure 23, and Figure 24.

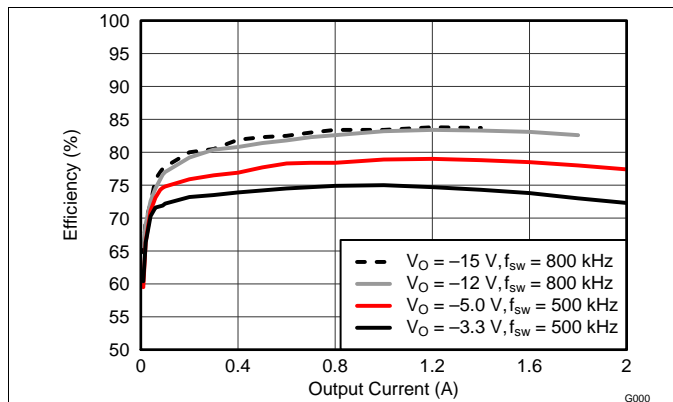


Figure 19. Efficiency vs. Output Current

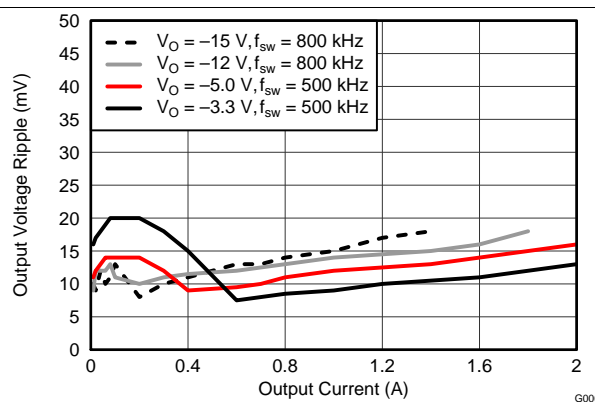


Figure 20. Voltage Ripple vs. Output Current

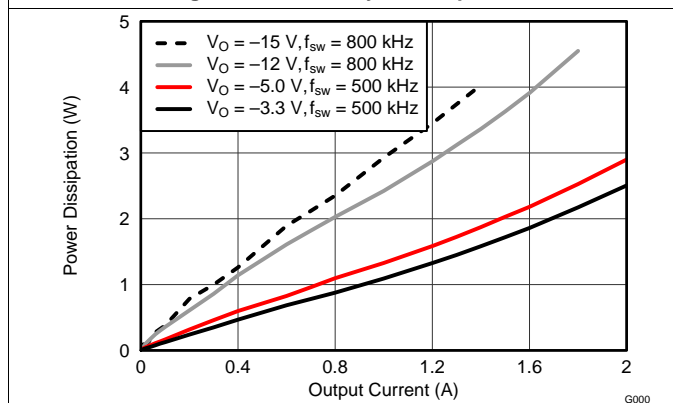


Figure 21. Power Dissipation vs. Output Current

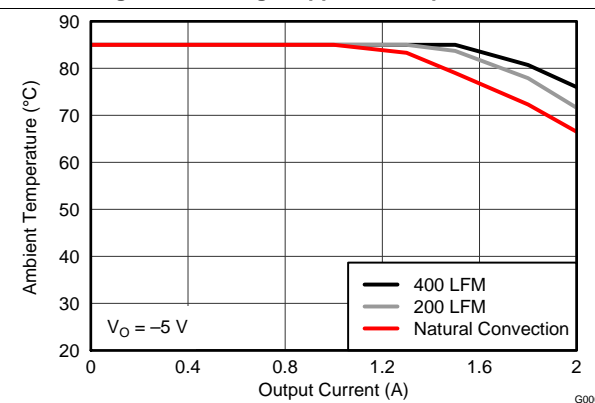


Figure 22. Safe Operating Area

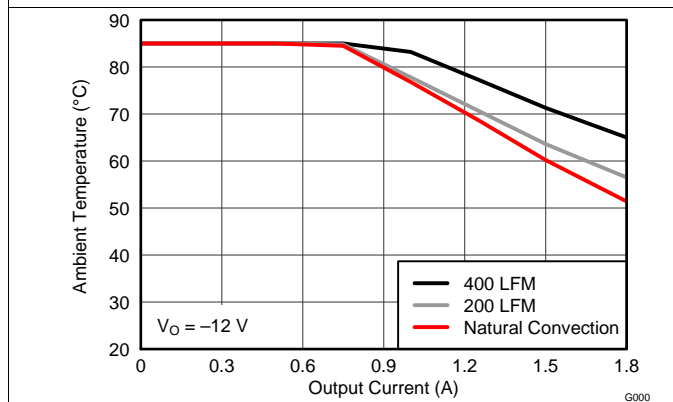


Figure 23. Safe Operating Area

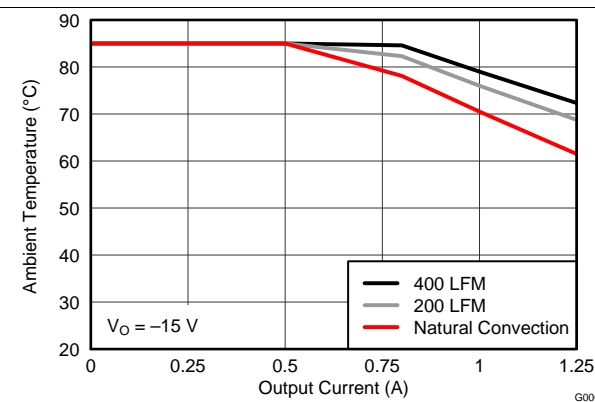
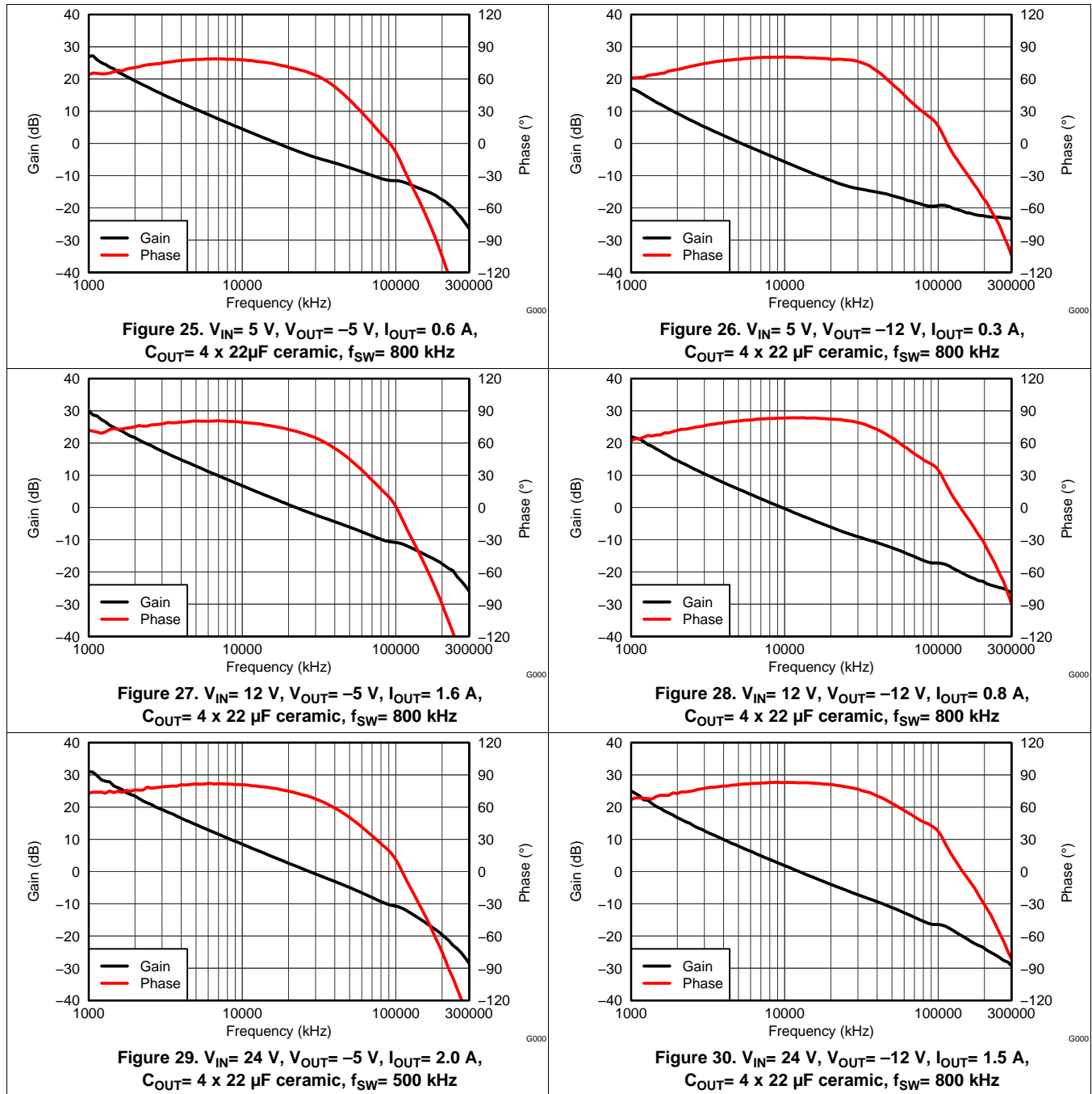


Figure 24. Safe Operating Area

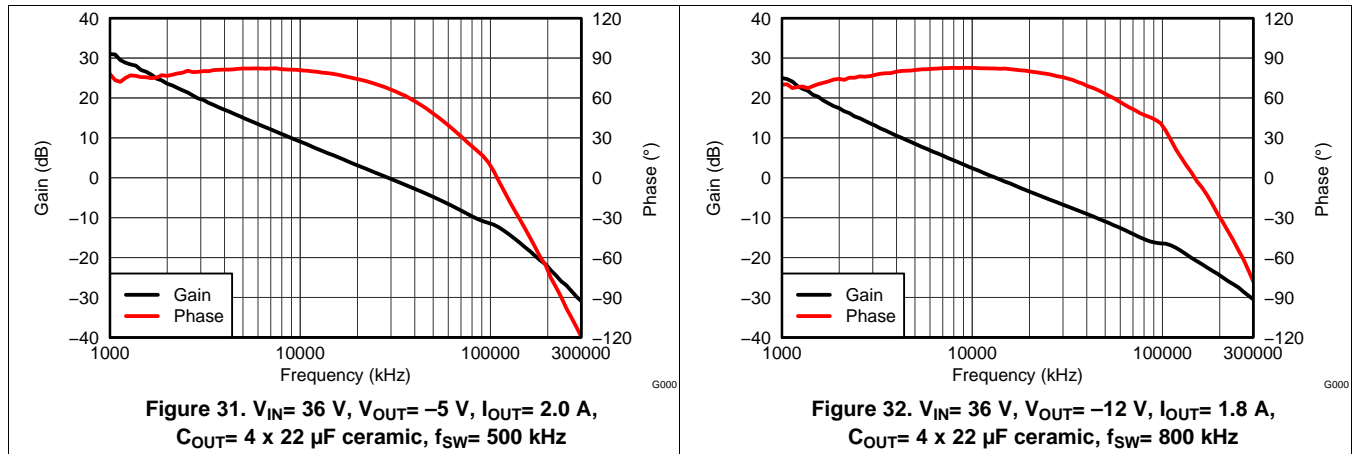
## 10 Typical Characteristics (Bode Plots)

The electrical characteristic data has been developed from actual products tested at 25°C. This data is considered typical for the converter.



**Typical Characteristics (Bode Plots) (continued)**

The electrical characteristic data has been developed from actual products tested at 25°C. This data is considered typical for the converter.



## 11 Capacitor Recommendations for the LMZ34002 Power Supply

### 11.1 Capacitor Technologies

#### 11.1.1 Electrolytic, Polymer-Electrolytic Capacitors

When using electrolytic capacitors, high-quality, computer-grade electrolytic capacitors are recommended. Polymer-electrolytic type capacitors are recommended for applications where the ambient operating temperature is less than 0°C. The Sanyo OS-CON capacitor series is suggested due to the lower ESR, higher rated surge, power dissipation, ripple current capability, and small package size. Aluminum electrolytic capacitors provide adequate decoupling over the frequency range of 2 kHz to 150 kHz, and are suitable when ambient temperatures are above 0°C.

#### 11.1.2 Ceramic Capacitors

The performance of aluminum electrolytic capacitors is less effective than ceramic capacitors above 150 kHz. Multilayer ceramic capacitors have a low ESR and a resonant frequency higher than the bandwidth of the regulator. They can be used to reduce the reflected ripple current at the input as well as improve the transient response of the output.

#### 11.1.3 Tantalum, Polymer-Tantalum Capacitors

Polymer-tantalum type capacitors are recommended for applications where the ambient operating temperature is less than 0°C. The Sanyo POSCAP series and Kemet T530 capacitor series are recommended rather than many other tantalum types due to their lower ESR, higher rated surge, power dissipation, ripple current capability, and small package size. Tantalum capacitors that have no stated ESR or surge current rating are not recommended for power applications.

### 11.2 Input Capacitor

The LMZ34002 requires a minimum input capacitance of 4.7 μF of ceramic type. The voltage rating of input capacitors must be greater than the maximum input voltage. The ripple current rating of the capacitor must be at least 450 mA rms. [Table 1](#) includes a preferred list of capacitors by vendor.

### 11.3 Output Capacitor

The required output capacitance of the LMZ34002 can be comprised of either all ceramic capacitors, or a combination of ceramic and bulk capacitors. The required output capacitance must include at least 2 × 47 μF of ceramic type (or 4 × 22 μF). The voltage rating of output capacitors must be greater than the output voltage. When adding additional non-ceramic bulk capacitors, low-ESR devices like the ones recommended in [Table 1](#) are required. Additional capacitance above the required minimum is determined by actual transient deviation requirements. [Table 1](#) includes a preferred list of capacitors by vendor.

**Table 1. Recommended Input/Output Capacitors<sup>(1)</sup>**

VENDOR	SERIES	PART NUMBER	CAPACITOR CHARACTERISTICS		
			WORKING VOLTAGE (V)	CAPACITANCE (μF)	ESR <sup>(2)</sup> (mΩ)
Murata	X5R	GRM31CR61H225KA88L	50	2.2	2
TDK	X5R	C3216X5R1H475K	50	4.7	2
Murata	X5R	GRM32ER61E226K	16	22	2
TDK	X5R	C3225X5R0J476K	6.3	47	2
Murata	X5R	GRM32ER60J476M	6.3	47	2
Sanyo	POSCAP	16TQC68M	16	68	50
Sanyo	POSCAP	6TPE100MI	6.3	100	25
Kemet	T530	T530D227M006ATE006	6.3	220	6

(1) **Capacitor Supplier Verification, RoHS, Lead-free and Material Details**

Consult capacitor suppliers regarding availability, material composition, RoHS and lead-free status, and manufacturing process requirements for any capacitors identified in this table.

(2) Maximum ESR @ 100 kHz, 25°C.

## 12 Application Information

### 12.1 Adjusting the Output Voltage

The LMZ34002 is designed to provide output voltages from –3 V to –17 V. The output voltage is determined by the value of  $R_{SET}$ , which must be connected between the VADJ pin (Pin 36) and GND. Table 2 gives the standard external  $R_{SET}$  resistor for a number of common bus voltages.

**Table 2. Standard  $R_{SET}$  Resistor Values for Common Output Voltages**

OUTPUT VOLTAGE $V_{OUT}$ (V)	–3.3	–5.0	–8.0	–12.0	–15.0
$R_{SET}$ (k $\Omega$ )	31.6	52.3	90.9	140	178

For other output voltages the value of  $R_{SET}$  can be calculated using the following formula, or simply selected from the range of values given in Table 3.

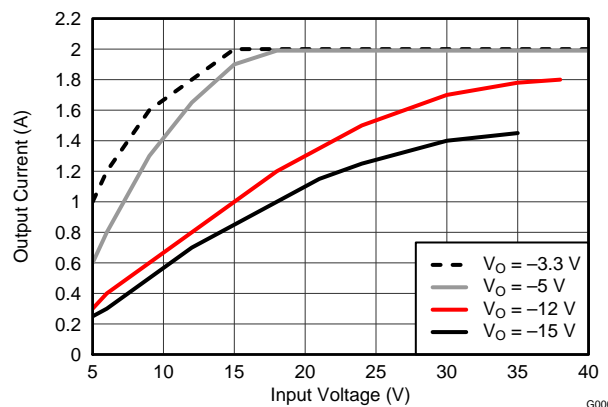
$$R_{SET} = 10 \times \left( \frac{|V_{OUT}|}{0.798} - 1 \right) \text{ (k}\Omega\text{)} \quad (1)$$

**Table 3. Standard  $R_{SET}$  Resistor Values**

$V_{OUT}$ (V)	$R_{SET}$ (k $\Omega$ )	$V_{OUT}$ (V)	$R_{SET}$ (k $\Omega$ )	$V_{OUT}$ (V)	$R_{SET}$ (k $\Omega$ )
–3.0	27.4	–7.5	84.5	–12.5	147
–3.3	31.6	–8.0	90.9	–13.0	154
–3.5	34.0	–8.5	97.6	–13.5	158
–4.0	40.2	–9.0	102	–14.0	165
–4.5	46.4	–9.5	110	–14.5	174
–5.0	52.3	–10.0	115	–15.0	178
–5.5	59.0	–10.5	121	–15.5	187
–6.0	64.9	–11.0	127	–16.0	191
–6.5	71.5	–11.5	133	–16.5	196
–7.0	78.7	–12.0	140	–17.0	205

### 12.2 Safe Operating Current

The amount of output current that can safely be delivered by the LMZ34002 depends on the input voltage and the output voltage. Figure 33 shows the maximum output current for four standard output voltages over input voltage.



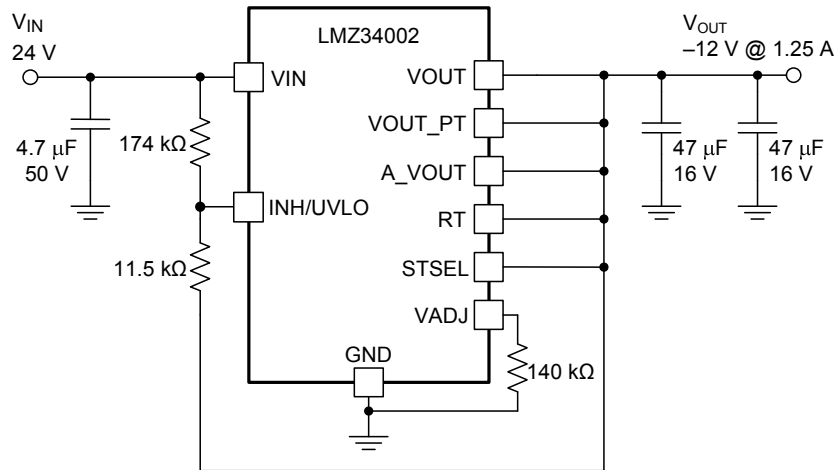
**Figure 33. Safe Operating Current**

**LMZ34002**

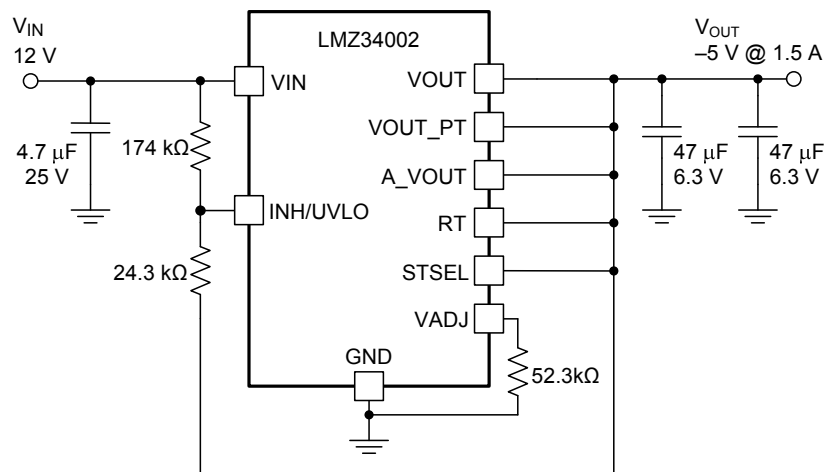
JAJSBV5C – JULY 2013 – REVISED APRIL 2018

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**12.3 Application Schematics**



**Figure 34. Typical Schematic**  
 $V_{IN} = 24 \text{ V}$ ,  $V_{OUT} = -12 \text{ V}$



**Figure 35. Typical Schematic**  
 $V_{IN} = 12 \text{ V}$ ,  $V_{OUT} = -5 \text{ V}$



## 12.4 Custom Design With WEBENCH® Tools

[Click here](#) to create a custom design using the LMZ34002 device with the WEBENCH® Power Designer.

1. Start by entering the input voltage ( $V_{IN}$ ), output voltage ( $V_{OUT}$ ), and output current ( $I_{OUT}$ ) requirements.
2. Optimize the design for key parameters such as efficiency, footprint, and cost using the optimizer dial.
3. Compare the generated design with other possible solutions from Texas Instruments.

The WEBENCH Power Designer provides a customized schematic along with a list of materials with real-time pricing and component availability.

In most cases, these actions are available:

- Run electrical simulations to see important waveforms and circuit performance
- Run thermal simulations to understand board thermal performance
- Export customized schematic and layout into popular CAD formats
- Print PDF reports for the design, and share the design with colleagues

Get more information about WEBENCH tools at [www.ti.com/WEBENCH](http://www.ti.com/WEBENCH).

## 12.5 Input Voltage

The LMZ34002 operates over the input voltage range of 4.5 V to 40 V. The maximum input voltage is 40 V, however, the sum of  $V_{IN} + |V_{OUT}|$  must not exceed 50 V.

See the [Undervoltage Lockout \(UVLO\) Threshold](#) section of this datasheet for more information.

## 12.6 Undervoltage Lockout (UVLO) Threshold

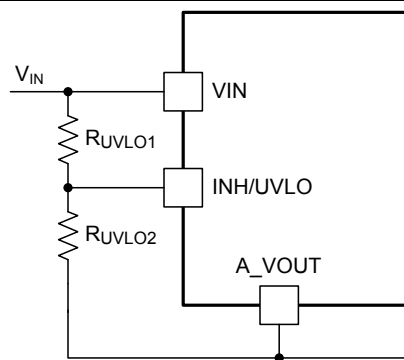
At turn-on, the  $V_{ON}$  UVLO threshold determines the input voltage level where the device begins power conversion.  $R_{UVLO1}$  and  $R_{UVLO2}$  set the turn-on threshold as shown in [Figure 36](#). The UVLO threshold is not present during the power-down sequence. Applications requiring a turn-off threshold must monitor the input voltage with external circuitry and shut-down using the INH control (see [Output On/Off Inhibit \(INH\)](#)).

The  $V_{ON}$  UVLO threshold must be set to at least 4.5 V to insure proper start-up and reduce current surges on the host input supply as the voltage rises. If possible, it is recommended to set the UVLO threshold to approximately 80 to 85% of the minimum expected input voltage.

Use [Equation 2](#) and [Equation 3](#) to calculate the values of  $R_{UVLO1}$  and  $R_{UVLO2}$ .  $V_{ON}$  is the voltage threshold during power-up when the input voltage is rising. [Table 4](#) lists standard resistor values for  $R_{UVLO1}$  and  $R_{UVLO2}$  for adjusting the  $V_{ON}$  UVLO threshold for several input voltages.

$$R_{UVLO1} = \frac{0.5}{2.9 \times 10^{-3}} \text{ (k}\Omega\text{)} \quad (2)$$

$$R_{UVLO2} = \frac{1.25}{\left(\frac{V_{ON} - 1.25}{R_{UVLO1}}\right) + 0.9 \times 10^{-3}} \text{ (k}\Omega\text{)} \quad (3)$$



**Figure 36. Adjustable VIN UVLO**

**Table 4. Standard Resistor Values to set  $V_{ON}$  UVLO Threshold**

$V_{ON}$ THRESHOLD (V)	4.5	5.0	6.5	8.0	9.0	10.0	15.0	20.0	30.0
$R_{UVLO1}$ (k $\Omega$ )	174	174	174	174	174	174	174	174	174
$R_{UVLO2}$ (k $\Omega$ )	63.4	56.2	40.2	31.6	27.4	24.3	15.8	11.5	7.50

## 12.7 Power-Up Characteristics

When configured as shown in the application schematics, the LMZ34002 produces a regulated output voltage following the application of a valid input voltage. During the power-up, internal soft-start circuitry slows the rate that the output voltage rises, thereby limiting the amount of in-rush current that can be drawn from the input source. The soft-start circuitry introduces a short time delay from the point that a valid input voltage is recognized. [Figure 37](#) shows the start-up waveforms for a LMZ34002, operating from a 12 V input and the output voltage adjusted to –5 V. The waveform were measured with a 1.5-A constant current load.

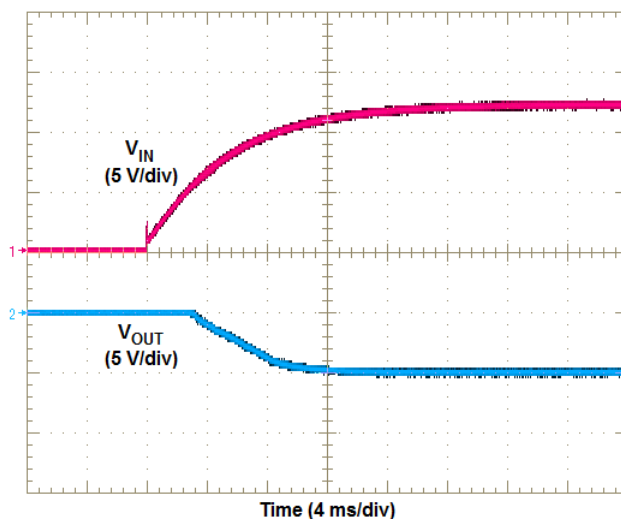


Figure 37. Start-Up Sequence

## 12.8 Light-Load Behavior

The LMZ34002 is a non-synchronous converter. One of the characteristics of non-synchronous operation is that as the output load current decreases, a point is reached where the energy delivered by a single switching pulse is more than the load can absorb. This energy causes the output voltage to rise slightly. This rise in output voltage is sensed by the feedback loop and the device responds by skipping one or more switching cycles until the output voltage falls back to the set point. At very light loads or no load, many switching cycles are skipped. The observed effect during this pulse skipping mode of operation is an increase in the peak to peak ripple voltage, and a decrease in the ripple frequency. The amount of load current when pulse skipping begins is a function of the input voltage, the output voltage, and the switching frequency.

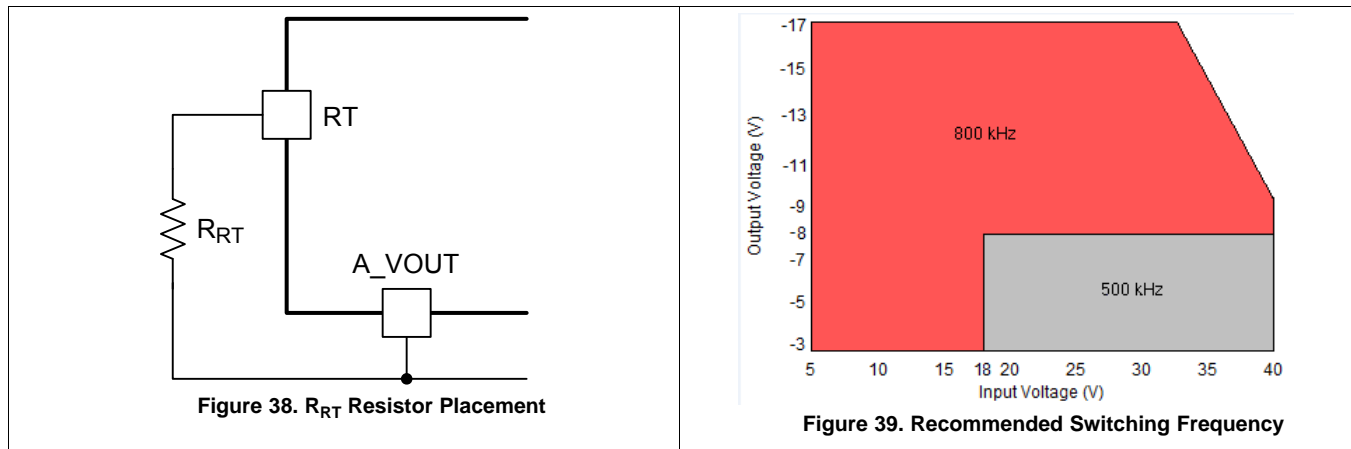
## 12.9 No-Load Operation

When operating at no load or very light load and the input voltage is removed, the output voltage discharges very slowly. If the input voltage is re-applied before the output voltage discharges, the slow-start circuit does not activate and the amount of inrush current is extremely large and may cause an over-current condition. To avoid this condition the output voltage must be allowed to discharge before re-applying the input voltage. Applying a 50-mA to 100-mA minimum load helps discharge the output voltage. Additionally, monitoring the input voltage with a supervisor and shutting-down using the INH control (see [Output On/Off Inhibit \(INH\)](#)) activates the internal slow-start circuit.

## 12.10 Switching Frequency

The recommended switching frequency of the LMZ34002 is 800 kHz. To operate at the recommended switching frequency, connect the RT pin (Pin 30) to A\_VOUT (at pin 32).

It is recommended to adjust the switching frequency in applications with both, higher input voltage (> 18V) and lower output voltage (< -8V). For these applications, improved operating performance can be obtained by decreasing the operating frequency to 500 kHz by adding a resistor,  $R_{RT}$  of 93.1 k $\Omega$  between the RT pin and A\_VOUT as shown in Figure 38. Figure 39 shows the recommended switching frequency over input voltage and output voltage.



**Table 5. Standard Resistor Values For Setting Switching Frequency**

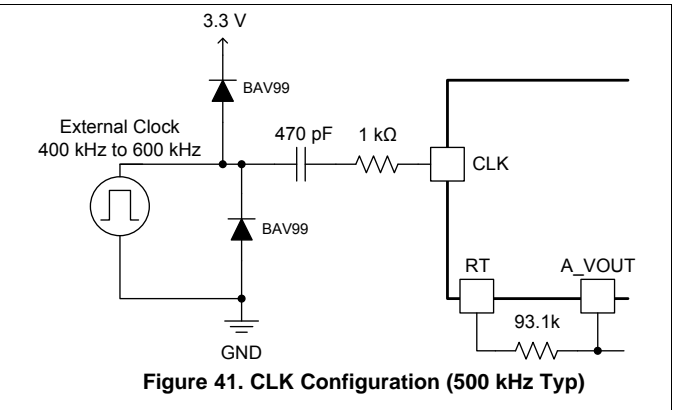
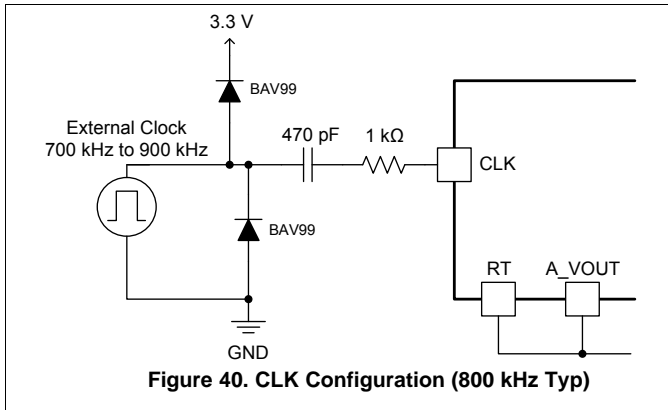
$f_{sw}$ (kHz)	500	800
$R_{RT}$ (k $\Omega$ )	93.1	0 (short)

## 12.11 Synchronization (CLK)

An internal phase locked loop (PLL) allows synchronization from 700 kHz to 900 kHz for 800 kHz applications, or 400 kHz to 600 kHz for 500 kHz applications. See Figure 39 to determine switching frequency based on input voltage and output voltage. To implement the synchronization feature, connect a square wave clock signal to the RT/CLK pin with a duty cycle between 25% to 75%. The clock signal amplitude must transition lower than 0.5 V and higher than 2.2 V. The start of the switching cycle is synchronized to the falling edge of RT/CLK pin. In applications requiring CLK mode, configure the device as shown in Figure 40 (800 kHz) and Figure 41 (500kHz).

Before the external clock is present, the device works in RT mode where the switching frequency is set by the  $R_{RT}$  resistor. When the external clock is present, the CLK mode overrides the RT mode. The first time the CLK pin is pulled above the RT/CLK high threshold (2.2 V), the device switches from RT mode to CLK mode and the CLK pin becomes high impedance as the PLL starts to lock onto the frequency of the external clock. It is not recommended to switch from CLK mode back to RT mode because the internal switching frequency drops to 100 kHz first before returning to the switching frequency set by the RT resistor.

**Synchronization (CLK) (continued)**

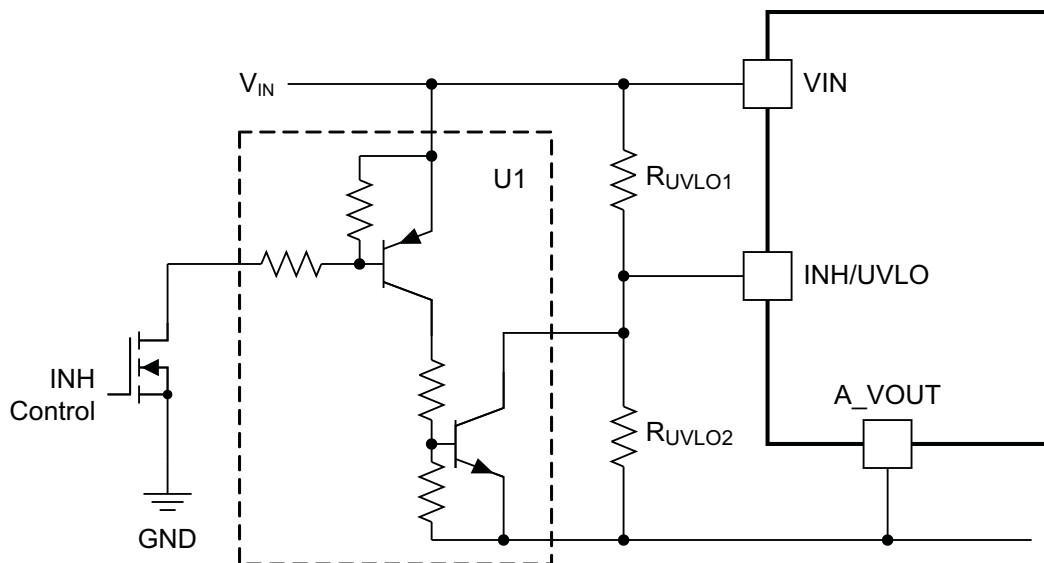


## 12.12 Output On/Off Inhibit (INH)

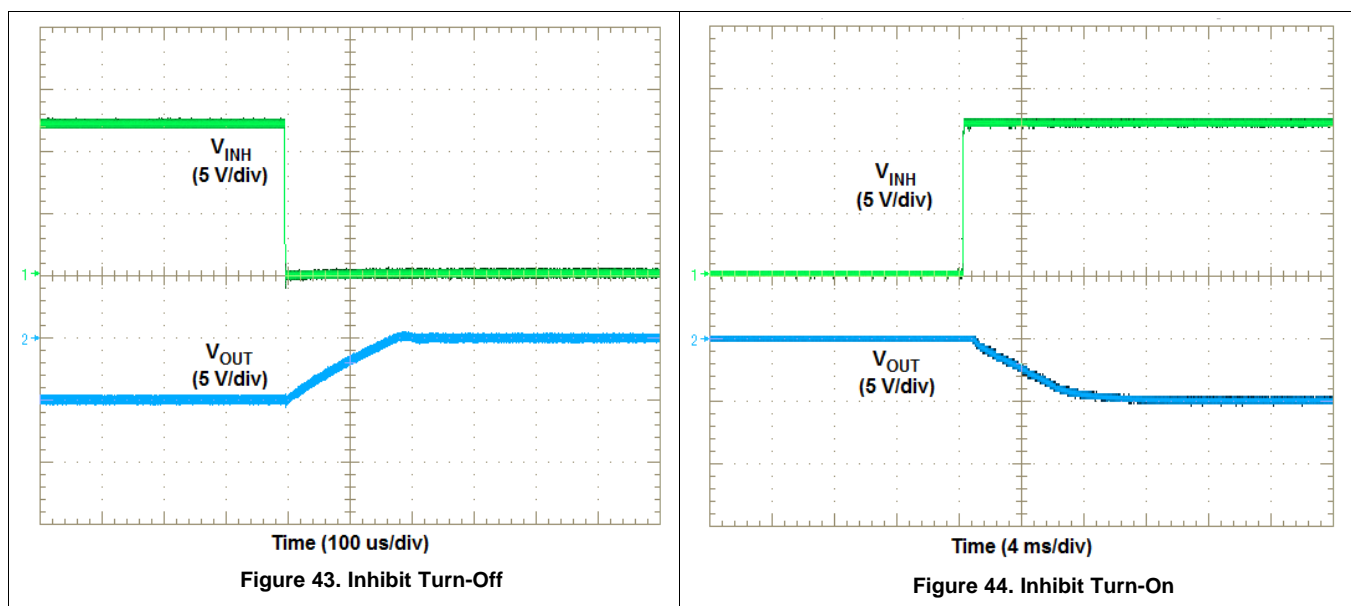
The INH pin provides electrical on/off control of the device. Once the INH pin voltage exceeds the threshold voltage, the device starts operation. If the INH pin voltage is pulled below the threshold voltage, the regulator stops switching and enters low quiescent current state.

The INH pin has an internal pull-up current source, allowing the user to float the INH pin for enabling the device. If an application requires controlling the INH pin, an external level-shifter is required to interface with the pin because in a positive-to-negative buck-boost supply, the INH pin is referenced to V<sub>OUT</sub>, not GND. Adding a level-shifter (U1) as shown in Figure 42, allows the INH control to be referenced to GND. A recommended level-shifter part # is DCX144EH-7 from Diodes Inc.

Pulling the input of U1 to GND applies a low voltage to the inhibit control pin and disables the output of the supply, shown in Figure 43. Releasing the input of U1 enables the device, which executes a soft-start power-up sequence, as shown in Figure 44. The device produces a regulated output voltage within 10 ms. The waveforms were measured with a 1.5-A constant current load.



**Figure 42. Typical Inhibit Control**



**Figure 43. Inhibit Turn-Off**

**Figure 44. Inhibit Turn-On**

### 12.13 Slow-Start Circuit (SS)

Connecting the STSEL pin (Pin 29) to A\_VOUT while leaving SS pin (Pin 28) open, enables the internal SS capacitor with a slow-start interval of approximately 10 ms. Adding additional SS capacitance between the SS pin and A\_VOUT increases the slow-start time. Figure 45 shows an additional SS capacitor connected to the SS pin and the STSEL pin connected to A\_VOUT. See Table 6 below for SS capacitor values and timing interval.

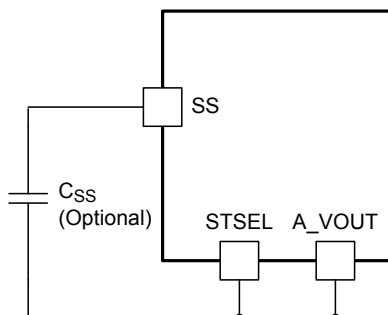


Figure 45. Slow-Start Capacitor (C<sub>SS</sub>) and STSEL Connection

Table 6. Slow-Start Capacitor Values and Slow-Start Time

C <sub>SS</sub> (nF)	open	10	15	22
SS Time (ms)	10	15	17	20

### 12.14 Inrush Current

During turn-on, as the LMZ34002 performs a slow-start sequence, an inrush current is induced as the output capacitors charge up. The inrush current is in addition to the DC input current. The amount of inrush current depends on the input voltage, output voltage and amount of output capacitance. Table 7 shows the typical inrush current for the input voltage, output voltage and the amount of output capacitance. Increasing the slow-start capacitor reduces the inrush current by slowing down the ramp of the output voltage. See Slow-Start Circuit (SS).

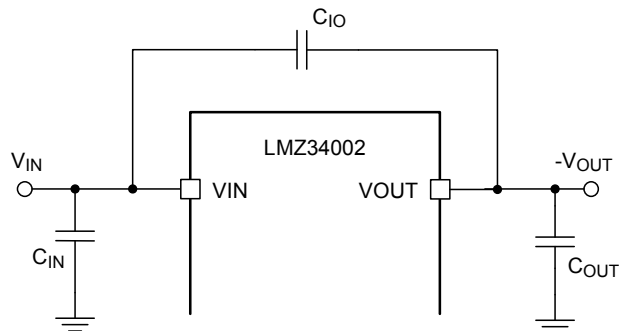
Table 7. Typical Inrush Current

Output Capacitance →		100 μF ceramic	200 μF <sup>(1)</sup>	320 μF <sup>(1)</sup>	430 μF <sup>(1)</sup>
V <sub>IN</sub> (V)	V <sub>OUT</sub> (V)	Inrush Current (A)			
5	-3.3	0.1	0.1	0.1	0.1
	-5	0.1	0.2	0.2	0.3
	-12	0.3	0.8	1.2	1.8
	-15	0.4	1.3	2.5	3.6
12	-3.3	0.1	0.1	0.1	0.1
	-5	0.1	0.1	0.1	0.2
	-12	0.2	0.4	0.6	0.8
	-15	0.3	0.5	0.9	1.3
24	-3.3	0.1	0.1	0.1	0.1
	-5	0.1	0.1	0.2	0.2
	-12	0.2	0.2	0.3	0.5
	-15	0.3	0.3	0.5	0.7
36	-3.3	0.2	0.2	0.2	0.2
	-5	0.2	0.2	0.2	0.2
	-12	0.2	0.3	0.4	0.4

(1) This amount of capacitance includes the required 100 μF of ceramic capacitance with additional bulk capacitance.

## 12.15 Input to Output Coupling Capacitor

Adding an input to output coupling capacitor ( $C_{IO}$ ) across  $V_{IN}$  to  $V_{OUT}$  as shown in Figure 46 can help reduce output voltage ripple and improve transient response. A typical value for  $C_{IO}$  is 2.2  $\mu\text{F}$  ceramic with a voltage rating greater than the sum of  $V_{IN} + |V_{OUT}|$ .



**Figure 46. Input to Output Coupling Capacitor**

## 12.16 Overcurrent Protection

For protection against load faults, the LMZ34002 incorporates cycle-by-cycle current limiting. During an overcurrent condition the output current is limited and the output voltage is reduced. If the output voltage drops more than 25%, the switching frequency is lowered to reduce power dissipation within the device. When the overcurrent condition is removed, the output voltage returns to the established voltage.

The LMZ34002 is not designed to endure a sustained short circuit condition. The use of an output fuse, voltage supervisor circuit, or other overcurrent protection circuit is recommended.

## 12.17 Thermal Shutdown

The internal thermal shutdown circuitry forces the device to stop switching if the junction temperature exceeds 180°C typically. The device reinitiates the power up sequence when the junction temperature drops below 165°C typically.



## 12.18 Layout Considerations

To achieve optimal electrical and thermal performance, an optimized PCB layout is required. Figure 47 through Figure 50 show four layers of a typical PCB layout. Some considerations for an optimized layout are:

- Use large copper areas for power planes (VIN, VOUT, and GND) to minimize conduction loss and thermal stress.
- Place ceramic input and output capacitors close to the module pins to minimize high frequency noise.
- Locate additional output capacitors between the ceramic capacitor and the load.
- Place a dedicated A\_VOUT copper area beneath the LMZ34002.
- Isolate the PH copper area from the GND copper area using the VOUT copper area.
- Connect the VOUT and A\_VOUT copper areas at one point; at pins 8 & 9.
- Place  $R_{SET}$ ,  $R_{RT}$ , and  $C_{SS}$  as close as possible to their respective pins.
- Use multiple vias to connect the power planes to internal layers.
- Use a dedicated sense line to connect  $R_{SET}$  to GND near the load for best regulation.

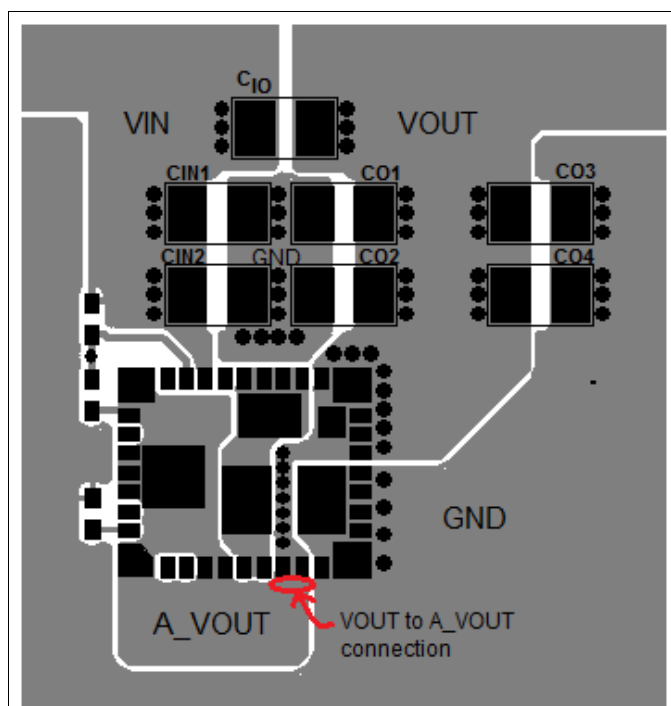


Figure 47. Typical Top-Layer Recommended Layout

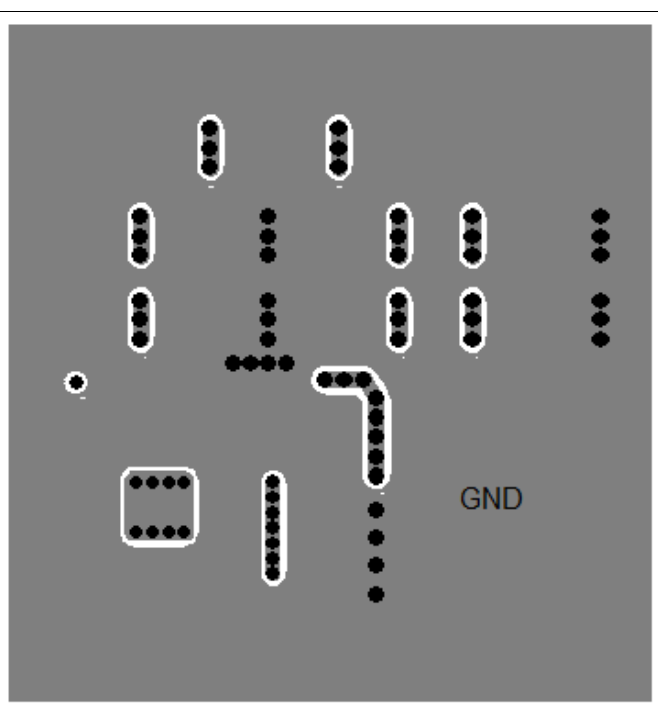
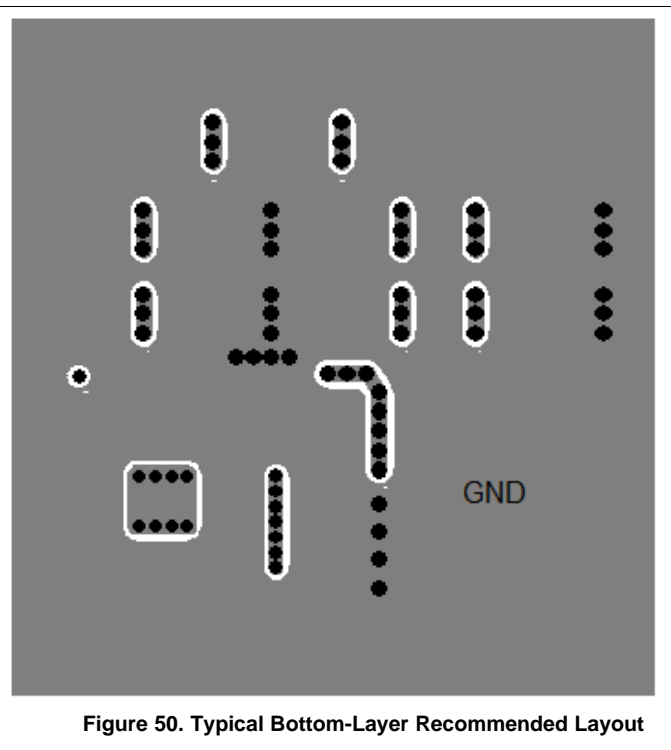
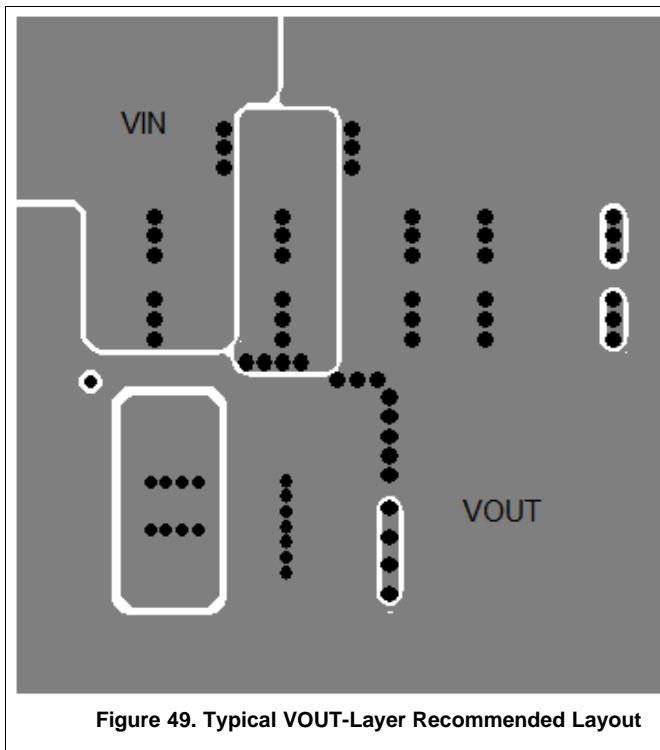


Figure 48. Typical GND-Layer Recommended Layout

Layout Considerations (continued)



12.19 EMI

The LMZ34002 complies with EN55022 Class B radiated emissions. Figure 51 shows a typical example of radiated emissions plots for the LMZ34002. The graph includes the plot of the antenna in the horizontal and vertical positions.

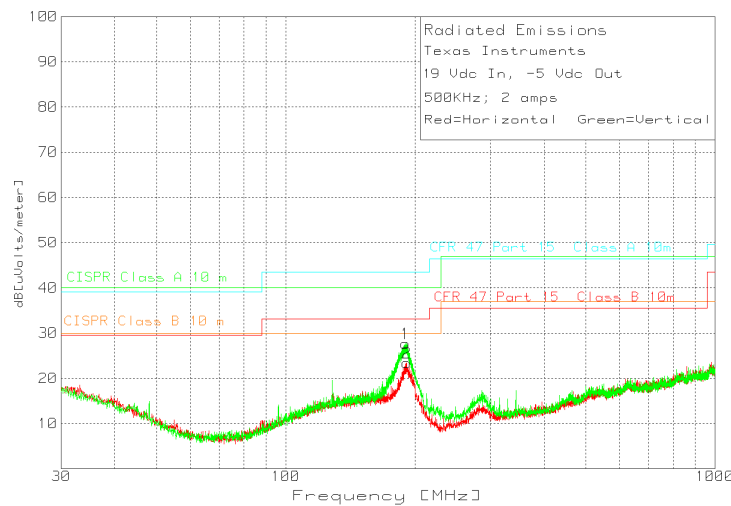


Figure 51. Radiated Emissions 19-V Input, -5-V Output, 2-A Load (EN55022 Class B)

## 13 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

<b>Changes from Revision B (June 2017) to Revision C</b>	<b>Page</b>
• LMZ34002用のWEBENCH®設計リンクを追加.....	1
• Increased the peak reflow temperature and maximum number of reflows to JEDEC specifications for improved manufacturability .....	2
• 「デバイス・サポート」セクションを追加 .....	28
<hr/>	
<b>Changes from Revision A (September 2013) to Revision B</b>	<b>Page</b>
• Added peak reflow and maximum number of reflows information .....	2
<hr/>	
<b>Changes from Original (JULY 2013) to Revision A</b>	<b>Page</b>
• Changed incorrect $R_{SET}$ value for $-5.5 V_{OUT}$ in <a href="#">Table 3</a> . .....	15

## 14 デバイスおよびドキュメントのサポート

### 14.1 デバイス・サポート

#### 14.1.1 開発サポート

##### 14.1.1.1 WEBENCH®ツールによるカスタム設計

[ここをクリック](#)すると、WEBENCH® Power Designerにより、LMZ34002を使用するカスタム設計を作成できます。

1. 最初に、入力電圧( $V_{IN}$ )、出力電圧( $V_{OUT}$ )、出力電流( $I_{OUT}$ )の要件を入力します。
2. オプティマイザのダイヤルを使用して、効率、占有面積、コストなどの主要なパラメータについて設計を最適化します。
3. 生成された設計を、テキサス・インスツルメンツが提供する他のソリューションと比較します。

WEBENCH Power Designerでは、カスタマイズされた回路図と部品リストを、リアルタイムの価格と部品の在庫情報と併せて参照できます。

ほとんどの場合、次の操作を実行可能です。

- 電氣的なシミュレーションを実行し、重要な波形と回路の性能を確認する。
- 熱シミュレーションを実行し、基板の熱特性を把握する。
- カスタマイズされた回路図やレイアウトを、一般的なCADフォーマットでエクスポートする。
- 設計のレポートをPDFで印刷し、同僚と設計を共有する。

WEBENCHツールの詳細は、[www.ti.com/WEBENCH](http://www.ti.com/WEBENCH)でご覧になれます。

### 14.2 ドキュメントのサポート

#### 14.2.1 関連資料

関連資料については、以下を参照してください。

『[BQFNパッケージのハンダ付け要件](#)』(SLTA069)

### 14.3 ドキュメントの更新通知を受け取る方法

ドキュメントの更新についての通知を受け取るには、[ti.com](http://ti.com)のデバイス製品フォルダを開いてください。右上の隅にある「通知を受け取る」をクリックして登録すると、変更されたすべての製品情報に関するダイジェストを毎週受け取れます。変更の詳細については、修正されたドキュメントに含まれている改訂履歴をご覧ください。

### 14.4 コミュニティ・リソース

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

**TI E2E™オンライン・コミュニティ** *TIのE2E ( Engineer-to-Engineer )* コミュニティ。エンジニア間の共同作業を促進するために開設されたものです。e2e.ti.comでは、他のエンジニアに質問し、知識を共有し、アイデアを検討して、問題解決に役立てることができます。

**設計サポート** *TIの設計サポート* 役に立つE2Eフォーラムや、設計サポート・ツールをすばやく見つけることができます。技術サポート用の連絡先情報も参照できます。

### 14.5 商標

E2E is a trademark of Texas Instruments.

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All other trademarks are the property of their respective owners.

### 14.6 静電気放電に関する注意事項



すべての集積回路は、適切なESD保護方法を用いて、取扱いと保存を行うようにして下さい。

静電気放電はわずかな性能の低下から完全なデバイスの故障に至るまで、様々な損傷を与えます。高精度の集積回路は、損傷に対して敏感であり、極めてわずかなパラメータの変化により、デバイスに規定された仕様に適合しなくなる場合があります。

## 14.7 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

## 15 メカニカル、パッケージ、および注文情報

以降のページには、メカニカル、パッケージ、および注文に関する情報が記載されています。この情報は、そのデバイスについて利用可能な最新のデータです。このデータは予告なく変更されることがあり、ドキュメントが改訂される場合もあります。本データシートのブラウザ版を使用されている場合は、画面左側の説明をご覧ください。

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
LMZ34002RKGR	ACTIVE	B1QFN	RKG	41	500	RoHS Exempt & Green	NIPDAU	Level-3-250C-168 HR	-40 to 85	(54260, LMZ34002)	<a href="#">Samples</a>
LMZ34002RKGT	ACTIVE	B1QFN	RKG	41	250	RoHS Exempt & Green	NIPDAU	Level-3-250C-168 HR	-40 to 85	(54260, LMZ34002)	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBsolete:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

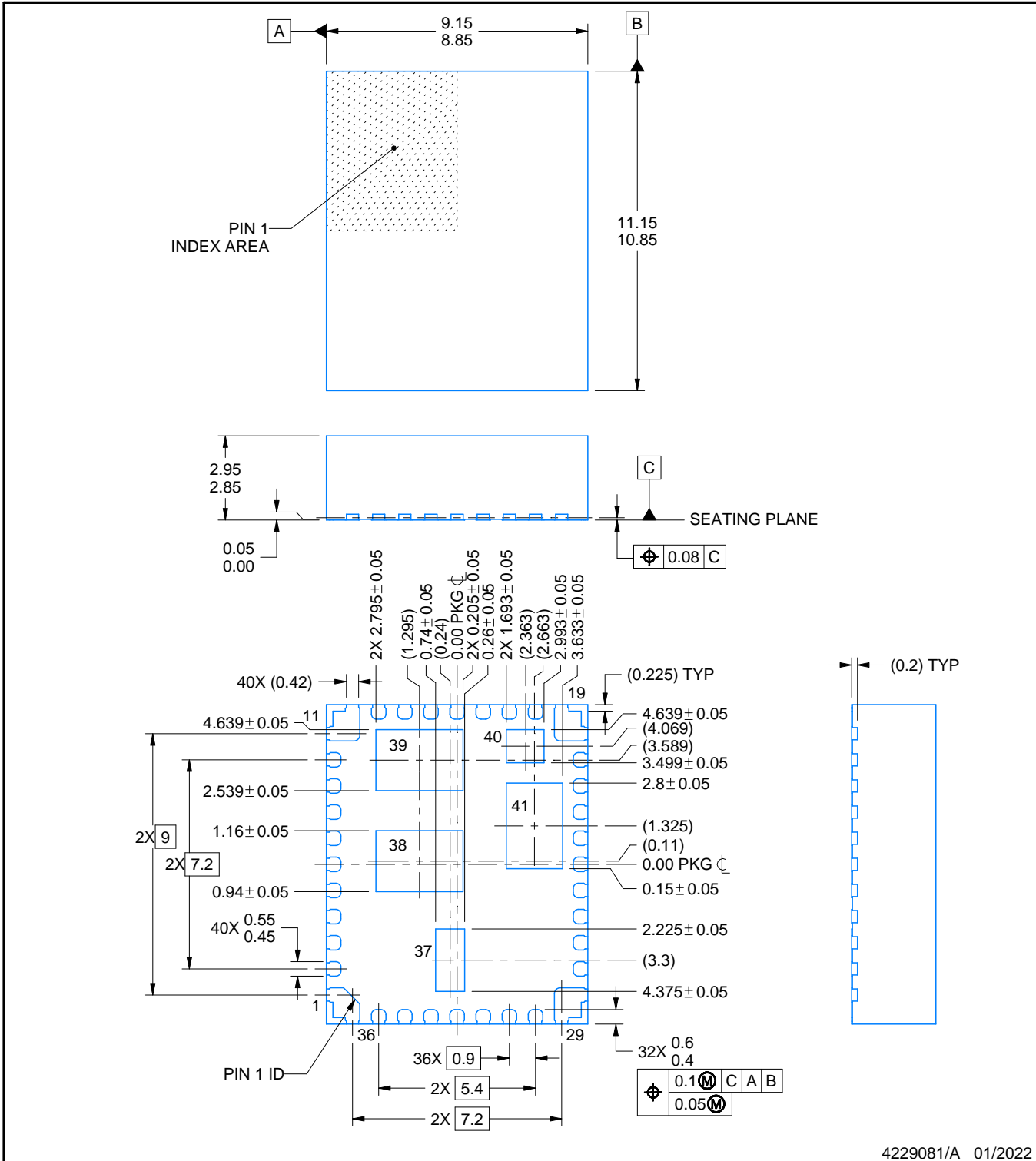
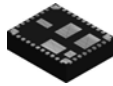
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LMZ34002RKGR	B1QFN	RKG	41	500	330.0	24.4	9.35	11.35	3.1	16.0	24.0	Q1
LMZ34002RKGT	B1QFN	RKG	41	250	330.0	24.4	9.35	11.35	3.1	16.0	24.0	Q1



**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LMZ34002RKGR	B1QFN	RKG	41	500	383.0	353.0	58.0
LMZ34002RKGT	B1QFN	RKG	41	250	383.0	353.0	58.0



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NOTES:

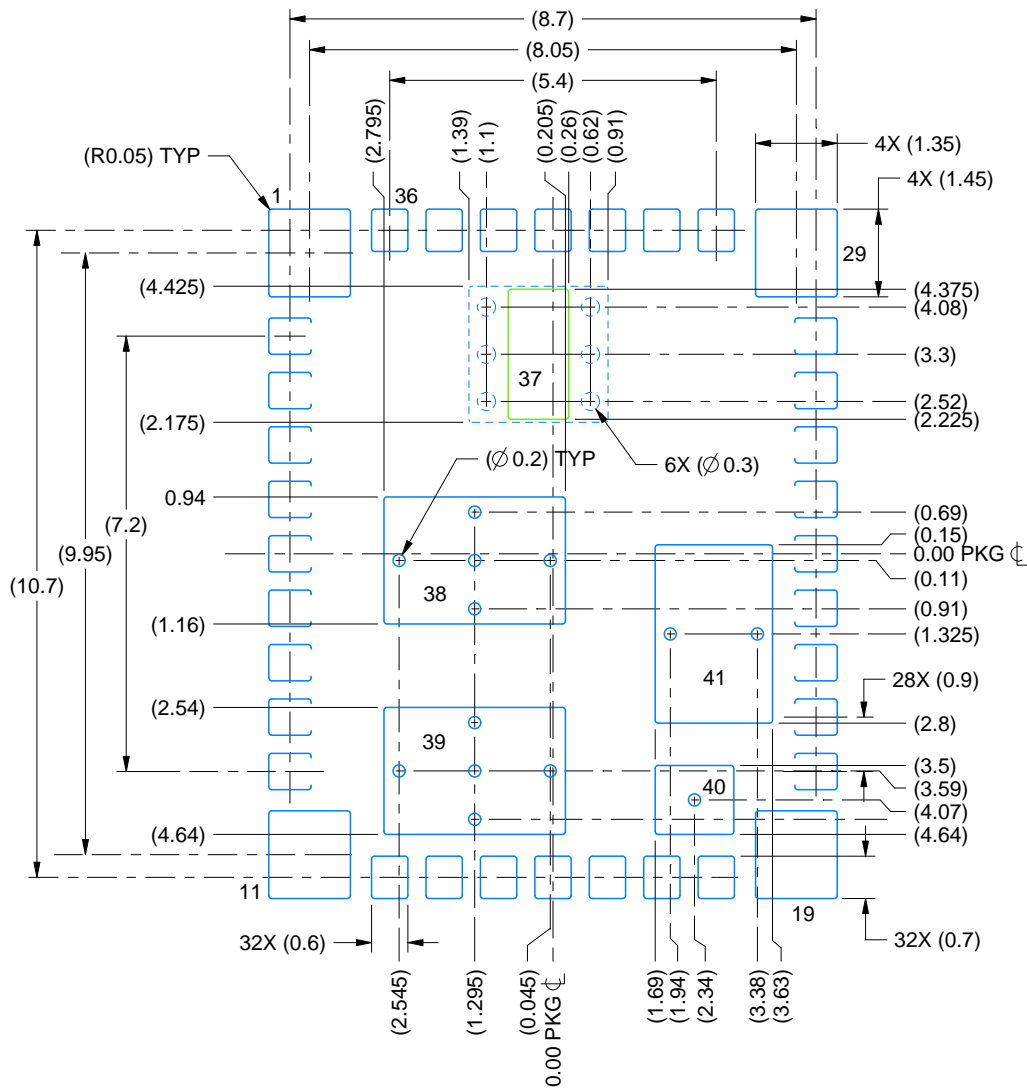
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pads must be soldered to the printed circuit board for optimal thermal and mechanical performance.

# EXAMPLE BOARD LAYOUT

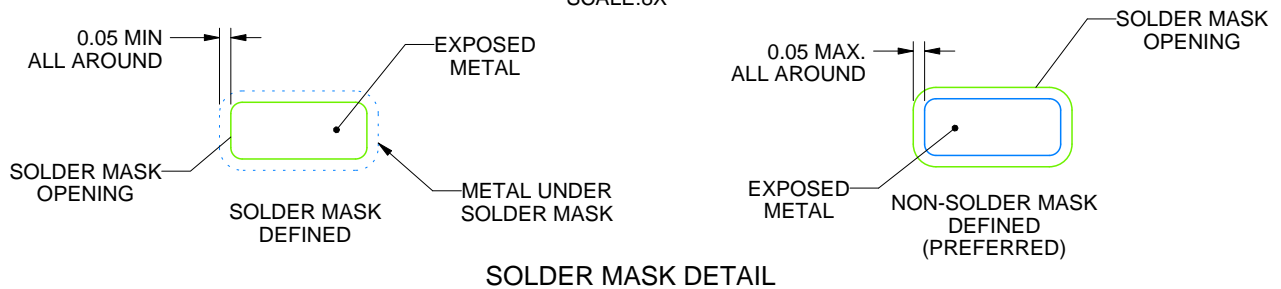
RKG0041A

B1QFN - 2.8 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:8X



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NOTES: (continued)

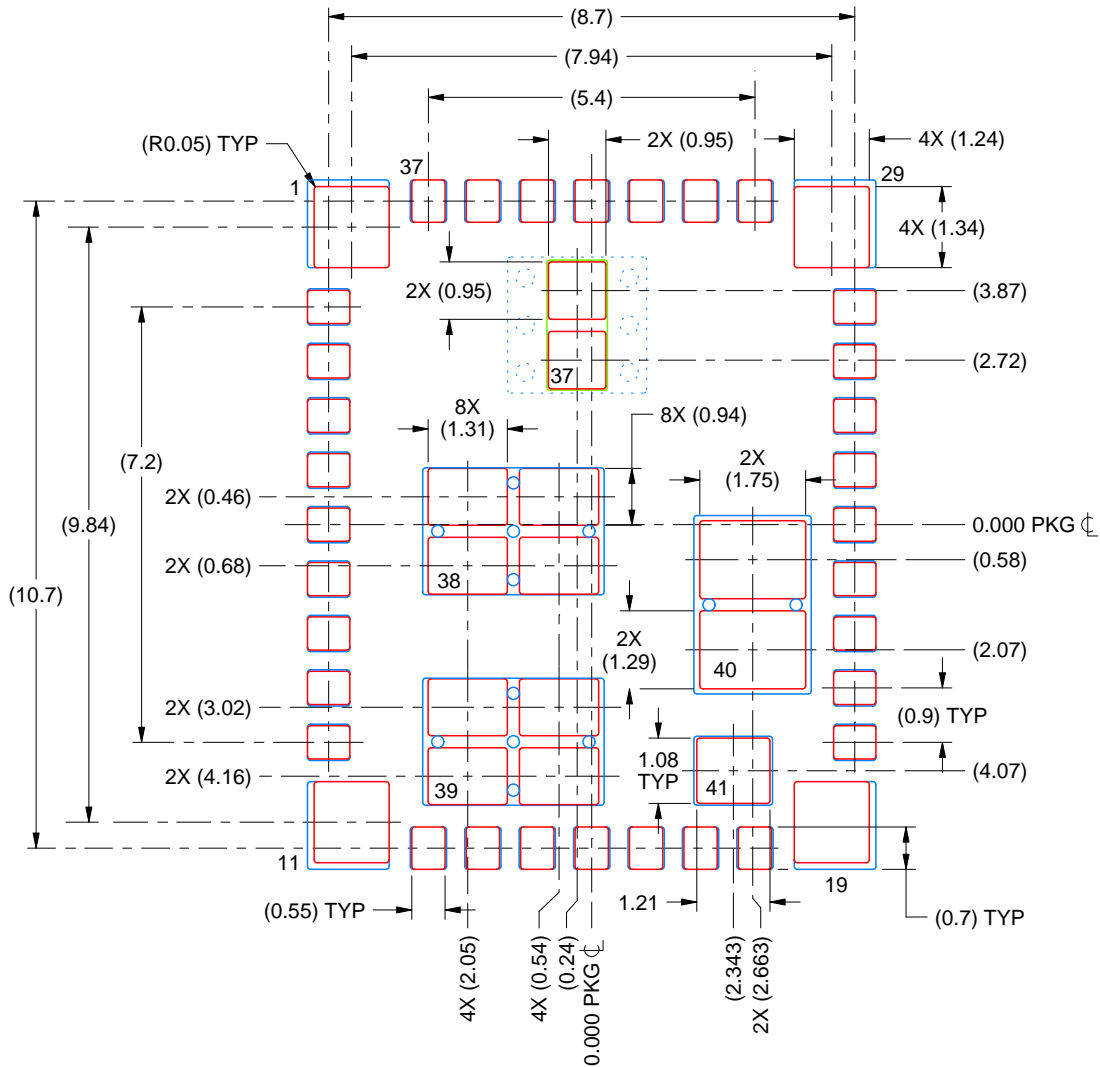
- This package designed to be soldered to a thermal pads on the board. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/slua271](http://www.ti.com/lit/slua271)).
- Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

# EXAMPLE STENCIL DESIGN

RKG0041A

B1QFN - 2.8 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



**SOLDER PASTE EXAMPLE**  
 BASED ON 0.1 mm STENCIL THICKNESS

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NOTES: (continued)

- 6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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